

Industrial Temperature USB 2.0 Flash Media Controller and USB Hub Combo

PRODUCT FEATURES

Datasheet

General Description

The SMSC USB2640i/USB2641i is a USB 2.0 compliant, Hi-Speed hub for USB port expansion with an attached mass storage class peripheral controller. The controller allows read/write capability to popular flash media from the following families:

- Secure Digital™ (SD)
- MultiMediaCard™ (MMC)
- xD-Picture Card™ (xD)¹
- Memory Stick® (MS)

The USB2640i/USB2641i is a fully integrated, single chip solution providing USB expansion and integrated flash card media reader/writer capability of ultra high performance operation. Average sustained transfer rates exceeding 35 MB/s are possible².

Highlights

- Hub controller with internally connected ultra fast flash media reader/writer and 2 exposed downstream ports for external peripheral expansion
- Flash media reader/writer employs multiplexed card interfaces which are optimized for use with single card insertion combo sockets
- Hardware-controlled data flow architecture for all self-mapped media
- Optional support for external firmware access via SPI interface
- **PortMap**
 - Flexible port mapping and port disable sequencing supports multiple platform designs
- **PortSwap**
 - Programmable USB differential-pair pin locations eases PCB design by aligning USB signal traces directly to connectors
- **PHYBoost**
 - Programmable USB transceiver drive strength recovers signal integrity

1.Support and capabilities for xD-Picture Card are not applicable for the USB2641i. Please obtain a user license from the xD-Picture Card License Office to support this flash media format.

2.Host and media dependent.

Features

- Compliant with the following flash media card specifications: SD 2.0 / MMC 4.2 / MS 1.43 / MS-Pro 1.02 / MS-PRO-HG 1.01 / MS-Duo 1.10 / xD 1.2
- Supports a single external 3.3 V supply source; internal regulators provide 1.8 V internal core voltage for additional bill of materials and power savings
- The transaction translator (TT) in the hub supports operation of Full-Speed and Low-Speed peripherals
- 9 K RAM | 64 K on-chip ROM
- Enhanced EMI rejection and ESD protection performance
- Onboard 24 MHz crystal driver circuit
- Optional external 24 MHz clock input
- Up to 9 GPIOs for special functions
- 8051 8-bit microprocessor
- Hub and flash media reader/writer configuration from a single source: External I²C ROM or external SPI ROM
 - Configures internal code using an external I²C EEPROM
 - Supports external code using a SPI Flash EEPROM
 - Customizable vendor ID, product ID, language ID
- EEPROM update via USB
- 48-pin QFN lead-free, RoHS compliant package (7x7 mm)
- The SMSC USB2640i/USB2641i supports the industrial temperature range of -40°C to 85°C

Applications

- Desktop and mobile PCs
- Personal mobile devices
- Printers
- GPS navigation systems
- Media Players/Viewers
- Consumer A/V
- Set-top boxes
- Industrial products

ORDER NUMBERS:**USB2640i/USB2641i-HZH-XX for 48-PIN, QFN LEAD-FREE ROHS COMPLIANT PACKAGE**

“XX” in the order number indicates the internal ROM firmware revision level.

Please contact your SMSC representative for more information.



80 ARKAY DRIVE, HAUPPAUGE, NY 11788 (631) 435-6000, FAX (631) 273-3123

Copyright © 2009 SMSC or its subsidiaries. All rights reserved.

Circuit diagrams and other information relating to SMSC products are included as a means of illustrating typical applications. Consequently, complete information sufficient for construction purposes is not necessarily given. Although the information has been checked and is believed to be accurate, no responsibility is assumed for inaccuracies. SMSC reserves the right to make changes to specifications and product descriptions at any time without notice. Contact your local SMSC sales office to obtain the latest specifications before placing your product order. The provision of this information does not convey to the purchaser of the described semiconductor devices any licenses under any patent rights or other intellectual property rights of SMSC or others. All sales are expressly conditional on your agreement to the terms and conditions of the most recently dated version of SMSC's standard Terms of Sale Agreement dated before the date of your order (the "Terms of Sale Agreement"). The product may contain design defects or errors known as anomalies which may cause the product's functions to deviate from published specifications. Anomaly sheets are available upon request. SMSC products are not designed, intended, authorized or warranted for use in any life support or other application where product failure could cause or contribute to personal injury or severe property damage. Any and all such uses without prior written approval of an Officer of SMSC and further testing and/or modification will be fully at the risk of the customer. Copies of this document or other SMSC literature, as well as the Terms of Sale Agreement, may be obtained by visiting SMSC's website at <http://www.smssc.com>. SMSC is a registered trademark of Standard Microsystems Corporation ("SMSC"). Product names and company names are the trademarks of their respective holders.

SMSC makes the following part-numbered device available for purchase only by customers who are xD-Picture Card licensees: USB2640i.

By purchasing or ordering any of such devices, Buyer represents, warrants, and agrees that Buyer is a duly licensed Licensee under an xD-Picture Card[™] License Agreement with Fuji Photo Film Co., Ltd., Olympus Optical Co., Ltd., and Toshiba Corporation; and that Buyer will maintain in effect such xD-Picture Card license and will give SMSC reasonable advance notice of any termination or expiration of such xD-Picture Card license, but in no event less than five days advance notice. SMSC may discontinue making such devices available for purchase by Buyer and/or discontinue further deliveries of such devices if such xD-Picture Card license shall expire, terminate, or cease to be in force, or if Buyer is or becomes in default of such xD-Picture Card license.

SMSC DISCLAIMS AND EXCLUDES ANY AND ALL WARRANTIES, INCLUDING WITHOUT LIMITATION ANY AND ALL IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, TITLE, AND AGAINST INFRINGEMENT AND THE LIKE, AND ANY AND ALL WARRANTIES ARISING FROM ANY COURSE OF DEALING OR USAGE OF TRADE. IN NO EVENT SHALL SMSC BE LIABLE FOR ANY DIRECT, INCIDENTAL, INDIRECT, SPECIAL, PUNITIVE, OR CONSEQUENTIAL DAMAGES; OR FOR LOST DATA, PROFITS, SAVINGS OR REVENUES OF ANY KIND; REGARDLESS OF THE FORM OF ACTION, WHETHER BASED ON CONTRACT; TORT; NEGLIGENCE OF SMSC OR OTHERS; STRICT LIABILITY; BREACH OF WARRANTY; OR OTHERWISE; WHETHER OR NOT ANY REMEDY OF BUYER IS HELD TO HAVE FAILED OF ITS ESSENTIAL PURPOSE, AND WHETHER OR NOT SMSC HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES.

Table of Contents

Chapter 1 Overview	7
1.1 Device Features	8
1.2 OEM Selectable Features	9
Chapter 2 Acronyms	10
Chapter 3 Pin Configurations	11
Chapter 4 Block Diagrams	13
Chapter 5 Pin Tables	15
5.1 48-Pin Tables	15
Chapter 6 Pin Descriptions	18
6.1 USB2640i/USB2641i Pin Descriptions	18
6.2 Buffer Type Descriptions	24
6.3 Port Power Control	25
6.4 ROM BOOT Sequence	27
Chapter 7 Configuration Options	28
7.1 Hub	28
7.1.1 Hub Configuration Options	28
7.1.2 VBus Detect	28
7.2 Card Reader	28
7.3 System Configurations	29
7.3.1 EEPROM/SPI Interface	29
7.3.2 EEPROM Data Descriptor	29
7.3.3 EEPROM Data Descriptor Register Descriptions	32
7.3.4 A0h-A7h: Device Power Configuration	36
7.3.5 Hub Controller Configurations	40
7.3.6 I ² C EEPROM	49
7.3.7 In-Circuit EEPROM Programming	49
7.4 Default Configuration Option:	49
7.5 Reset	49
7.5.1 Internal POR Hardware Reset	49
7.5.2 External Hardware nRESET	50
7.5.3 USB Bus Reset	51
Chapter 8 Pin Reset States	52
8.1 Pin Reset States	52
Chapter 9 AC Specifications	56
9.1 Oscillator/Crystal	56
9.2 Ceramic Resonator	57
9.3 External Clock	57
9.3.1 I ² C EEPROM	57
9.3.2 USB 2.0	57
Chapter 10 DC Parameters	58
10.1 Maximum Guaranteed Ratings	58
10.2 Operating Conditions	59

10.3	DC Electrical Characteristics	59
10.4	Capacitance $T_A = 25^{\circ}\text{C}$; $f_c = 1\text{ MHz}$; $V_{DD33} = 3.3\text{ V}$	61

Chapter 11	GPIO Usage	62
-------------------	-------------------------	-----------

Chapter 12	Package Outline	63
-------------------	------------------------------	-----------

List of Tables

Table 5.1	USB2640i 48-Pin Table	15
Table 5.2	USB2641i 48-Pin Table	16
Table 6.1	USB2640i/USB2641i Pin Descriptions	18
Table 6.2	USB2640i/USB2641i Buffer Type Descriptions	24
Table 7.1	Internal Flash Media Controller Configurations	29
Table 7.2	Hub Controller Configurations	31
Table 7.3	Other Internal Configurations	31
Table 7.4	Port Map Register for Ports 1 & 2	47
Table 7.5	Port Map Register for Port 3	48
Table 7.6	nRESET Timing for EEPROM Mode	50
Table 8.1	Legend for Pin Reset States Table	52
Table 8.2	USB2640i Pin Reset States	52
Table 8.3	USB2641i Pin Reset States	54
Table 9.1	Crystal Circuit Legend	56
Table 10.1	Pin Capacitance	61
Table 11.1	USB2640i/USB2641i GPIO Usage	62

List of Figures

Figure 3.1	USB2640i 48-Pin QFN	11
Figure 3.2	USB2641i 48-Pin QFN	12
Figure 4.1	USB2640i Block Diagram.	13
Figure 4.2	USB2641i Block Diagram.	14
Figure 6.1	Port Power Control with USB Power Switch	25
Figure 6.2	Port Power control with Poly Fuse	26
Figure 6.3	Port Power with Ganged Control with Poly Fuse	26
Figure 6.4	USB2640i/USB2641i SPI ROM Connection	27
Figure 6.5	USB2640i/USB2641i I ² C Connection	27
Figure 7.1	nRESET Timing for EEPROM Mode	50
Figure 8.1	Pin Reset States	52
Figure 9.1	Typical Crystal Circuit	56
Figure 9.2	Capacitance Formulas	56
Figure 9.3	Ceramic Resonator Usage with SMSC IC	57
Figure 10.1	Supply Rise Time Models	58
Figure 12.1	USB2640i/USB2641i 48-Pin QFN	63

Chapter 1 Overview

The SMSC USB2640i/USB2641i is an integrated USB 2.0 compliant, Hi-Speed hub for USB port expansion with an attached bulk only mass storage class peripheral controller. This multi-format flash media controller and USB Hub Combo features three downstream ports: one port is dedicated to an internally connected ultra fast flash media reader/writer and two exposed downstream ports are available for external peripheral expansion.

The SMSC USB2640i/USB2641i is an ultra fast, OEM-configurable, hub controller IC with three downstream ports for embedded USB solutions. The USB2640i/USB2641i will attach to an upstream port as a Full-Speed Hub or as a Full-/Hi-Speed Hub. The hub supports Low-Speed, Full-Speed, and Hi-Speed (if operating as a Hi-Speed Hub) downstream devices on all of the enabled downstream ports.

All required resistors on the USB ports are integrated into the hub. This includes all series termination resistors on D+ and D– pins and all required pull-down and pull-up resistors on D+ and D– pins. The over-current sense inputs for the downstream facing ports have internal pull-up resistors.

The USB2640i/USB2641i includes programmable features such as:

PortMap which provides flexible port mapping and disable sequences. The downstream ports of a USB2640i/USB2641i hub can be reordered or disabled in any sequence to support multiple platform designs with minimum effort. For any port that is disabled, the USB2640i/USB2641i automatically reorders the remaining ports to match the USB host controller's port numbering scheme.

PortSwap which adds per-port programmability to USB differential-pair pin locations. PortSwap allows direct alignment of USB signals (D+/D–) to connectors avoiding uneven trace length or crossing of the USB differential signals on the PCB.

PHYBoost which enables four programmable levels of USB signal drive strength in downstream port transceivers. PHYBoost attempts to restore USB signal integrity that has been compromised by system level variables such as poor PCB layout, long cables, etc.

1.1 Device Features

Hardware Features

- Single chip flash media controller
- The SMSC USB2640i/USB2641i supports the industrial temperature range of -40°C to 85°C
- Transaction translator (TT) in the hub supports operation of FS and LS peripherals
- Full power management with individual or ganged power control of each downstream port
- Optional support for external firmware access via SPI interface
 - 30 MHz or 60 MHz operation support
 - Single bit or dual bit mode support
 - Mode 0 or mode 3 SPI support

Compliant with the following flash media card specifications:

- Secure Digital 2.0 / MultiMediaCard 4.2
 - SD 2.0, HS-SD, HC-SD
 - TransFlash[™] and reduced form factor media
 - 1/4/8 bit MMC 4.2
- SDIO and MMC streaming mode support
- Memory Stick 1.43
- Memory Stick Pro Format 1.02
- Memory Stick Pro-HG Duo Format 1.01
 - Memory Stick, MS Duo, HS-MS, MS Pro-HG, MS Pro
- Memory Stick Duo 1.10
- xD-Picture Card 1.2 (USB2640i only)
- On board 24 MHz crystal driver circuit
- Optional external 24 MHz clock input
 - Must be used with an external resistor divider to provide a 1.8 V signal
- Up to 9 GPIOs: Configuration and polarity for special function use such as LED indicators, button inputs, and power control to memory devices
 - The number of actual GPIOs depends on the implementation configuration used
 - One GPIO available with up to 200 mA drive and protected “fold-back” short circuit current
- 8051 8-bit microprocessor
 - 60 MHz - single cycle execution
 - 64 KB ROM; 9 KB RAM
- Internal regulator for 1.8 V core operation
- Optimized pinout improves signal flow, easing implementation and allowing for improved signal integrity treatment

Software Features

- Optimized for low latency interrupt handling
- Hub and flash media reader/writer configuration from a single source: External I²C ROM or external SPI ROM
- EEPROM update via USB
- Please see the USB2640i/USB2641i Software Release Notes for additional software features

1.2 OEM Selectable Features

Hub

A default configuration is available in USB2640i/USB2641i following a reset. The USB2640i/USB2641i may also be configured by an external I²C EEPROM or via external SPI ROM flash.

The USB2640i/USB2641i supports several OEM selectable features:

- Compound Device support (port is permanently hardwired to a downstream USB peripheral device), on a port-by-port basis.
- Select over-current sensing and port power control on an individual (port-by-port) or ganged (all ports together) basis to match the OEM's choice of circuit board component selection.
- Port power control and over-current detection/delay features
- Configure the delay time for filtering the over-current sense inputs.
- Configure the delay time for turning on downstream port power.
- Bus- or self-powered selection
- Hub port disable or non-removable configurations
- Flexible port mapping and disable sequence. Ports can be disabled/reordered in any sequence to support multiple platforms with a single design. The hub will automatically reorder the remaining ports to match the host controller's numbering scheme.
- Programmable USB differential-pair pin location.
 - Eases PCB layout by aligning USB signal lines directly to connectors
- Programmable USB signal drive strength. Recover USB signal integrity due to compromised system environments using four levels of signal drive strength.
- Indicate the maximum current that the 2-port hub consumes from the USB upstream port.
- Indicate the maximum current required for the hub controller.

Flash Media Controller

- Customize vendor ID, product ID, and device ID.
- 12-hex digit (max) serial number string
- Customizable vendor specific data by optional use of external serial EEPROM
- 28-character manufacturer ID and product string for flash media reader/writer
- LED blink interval or duration

Chapter 2 Acronyms

FM:	Flash Media
FMC:	Flash Media Controller
FS:	Full-speed Device
LS:	Low-speed Device
HS:	Hi-speed Device
I²C[®]:	Inter-Integrated Circuit ¹
MMC:	MultiMediaCard
MS:	Memory Stick
MSC:	Memory Stick Controller
OCS:	Over-current Sense
RXD:	Received eXchange Data
SD:	Secure Digital
SDC:	Secure Digital Controller
TXD:	Transmit eXchange Data
UART:	Universal Asynchronous Receiver-Transmitter
UCHAR:	Unsigned Character
UINT:	Unsigned Integer
xD:	xD-Picture Card

Standard Microsystems is a registered trademark and SMSC is a trademark of Standard Microsystems Corporation. Other product and company names are trademarks or registered trademarks of their respective holders.

*Note: In order to develop, make, use, or sell readers and/or other products using or incorporating any of the SMSC devices made the subject of this document or to use related SMSC software programs, technical information and licenses under patent and other intellectual property rights from or through various persons or entities, including without limitation media standard companies, forums, and associations, and other patent holders may be required. These media standard companies, forums, and associations include without limitation the following: Sony Corporation (Memory Stick, Memory Stick Pro); SD3 LLC (Secure Digital); MultiMedia Card Association (MultiMediaCard); the SSFDC Forum (SmartMedia); the Compact Flash Association (Compact Flash); and Fuji Photo Film Co., Ltd., Olympus Optical Co., Ltd., and Toshiba Corporation (xD-Picture Card). SMSC does not make such licenses or technical information available; does not promise or represent that any such licenses or technical information will actually be obtainable from or through the various persons or entities (including the media standard companies, forums, and associations), or with respect to the terms under which they may be made available; and is not responsible for the accuracy or sufficiency of, or otherwise with respect to, any such technical information.

SMSC's obligations (if any) under the Terms of Sale Agreement, or any other agreement with any customer, or otherwise, with respect to infringement, including without limitation any obligations to defend or settle claims, to reimburse for costs, or to pay damages, shall not apply to any of the devices made the subject of this document or any software programs related to any of such devices, or to any combinations involving any of them, with respect to infringement or claimed infringement of any existing or future patents related to solid state disk or other flash memory technology or applications ("Solid State Disk Patents"). By making any purchase of any of the devices made the subject of this document, the customer represents, warrants, and agrees that it has obtained all necessary licenses under then-existing Solid State Disk Patents for the manufacture, use and sale of solid state disk and other flash memory products and that the customer will timely obtain at no cost or expense to SMSC all necessary licenses under Solid State Disk Patents; that the manufacture and testing by or for SMSC of the units of any of the devices made the subject of this document which may be sold to the customer, and any sale by SMSC of such units to the customer, are valid exercises of the customer's rights and licenses under such Solid State Disk Patents; that SMSC shall have no obligation for royalties or otherwise under any Solid State Disk Patents by reason of any such manufacture, use, or sale of such units; and that SMSC shall have no obligation for any costs or expenses related to the customer's obtaining or having obtained rights or licenses under any Solid State Disk Patents.

SMSC MAKES NO WARRANTIES, EXPRESS, IMPLIED, OR STATUTORY, IN REGARD TO INFRINGEMENT OR OTHER VIOLATION OF INTELLECTUAL PROPERTY RIGHTS. SMSC DISCLAIMS AND EXCLUDES ANY AND ALL WARRANTIES AGAINST INFRINGEMENT AND THE LIKE.

No license is granted by SMSC expressly, by implication, by estoppel or otherwise, under any patent, trademark, copyright, mask work right, trade secret, or other intellectual property right. **To obtain this software program the appropriate SMSC Software License Agreement must be executed and in effect. Forms of these Software License Agreements may be obtained by contacting SMSC.

1. I²C is a registered trademark of Philips Corporation.

Chapter 3 Pin Configurations

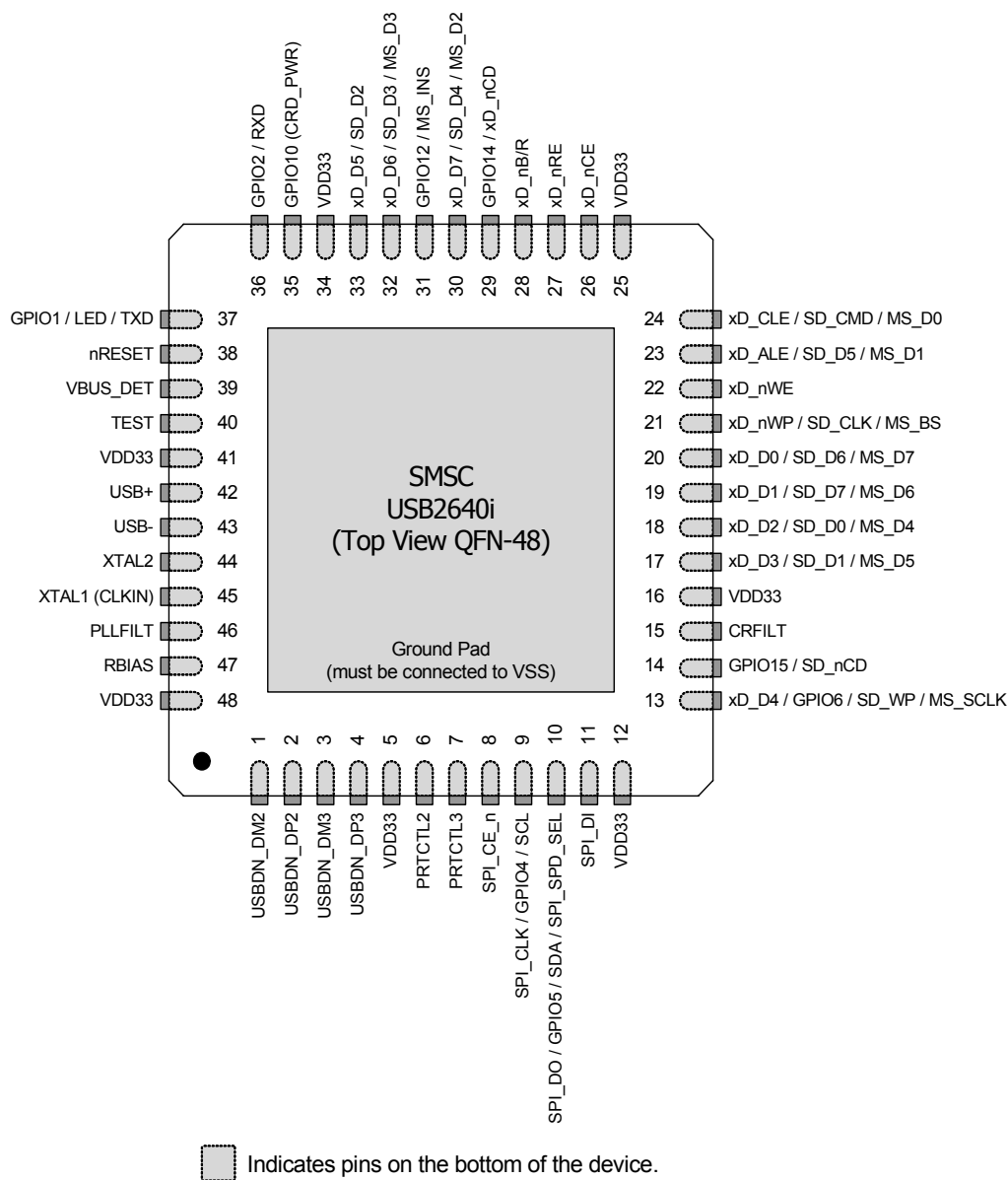


Figure 3.1 USB2640i 48-Pin QFN

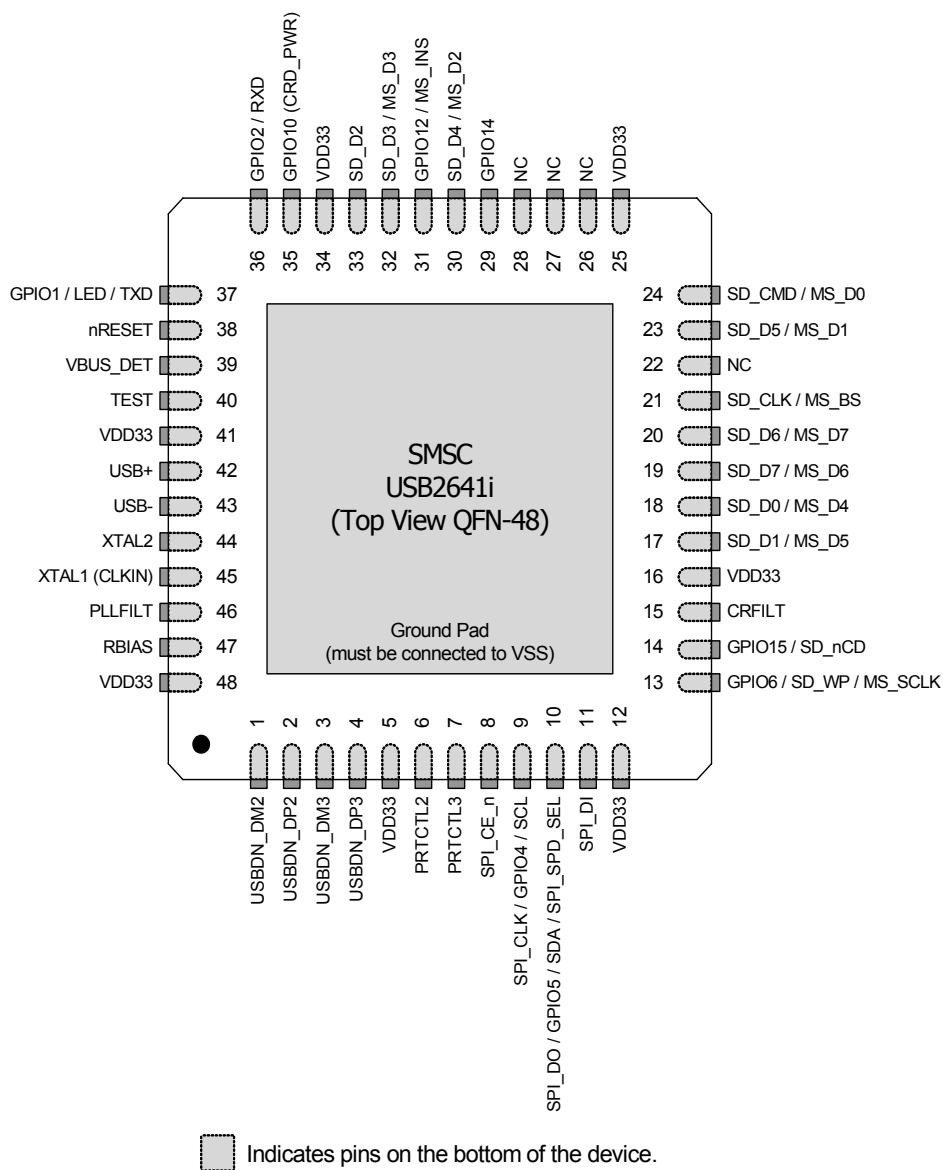


Figure 3.2 USB2641i 48-Pin QFN

Chapter 4 Block Diagrams

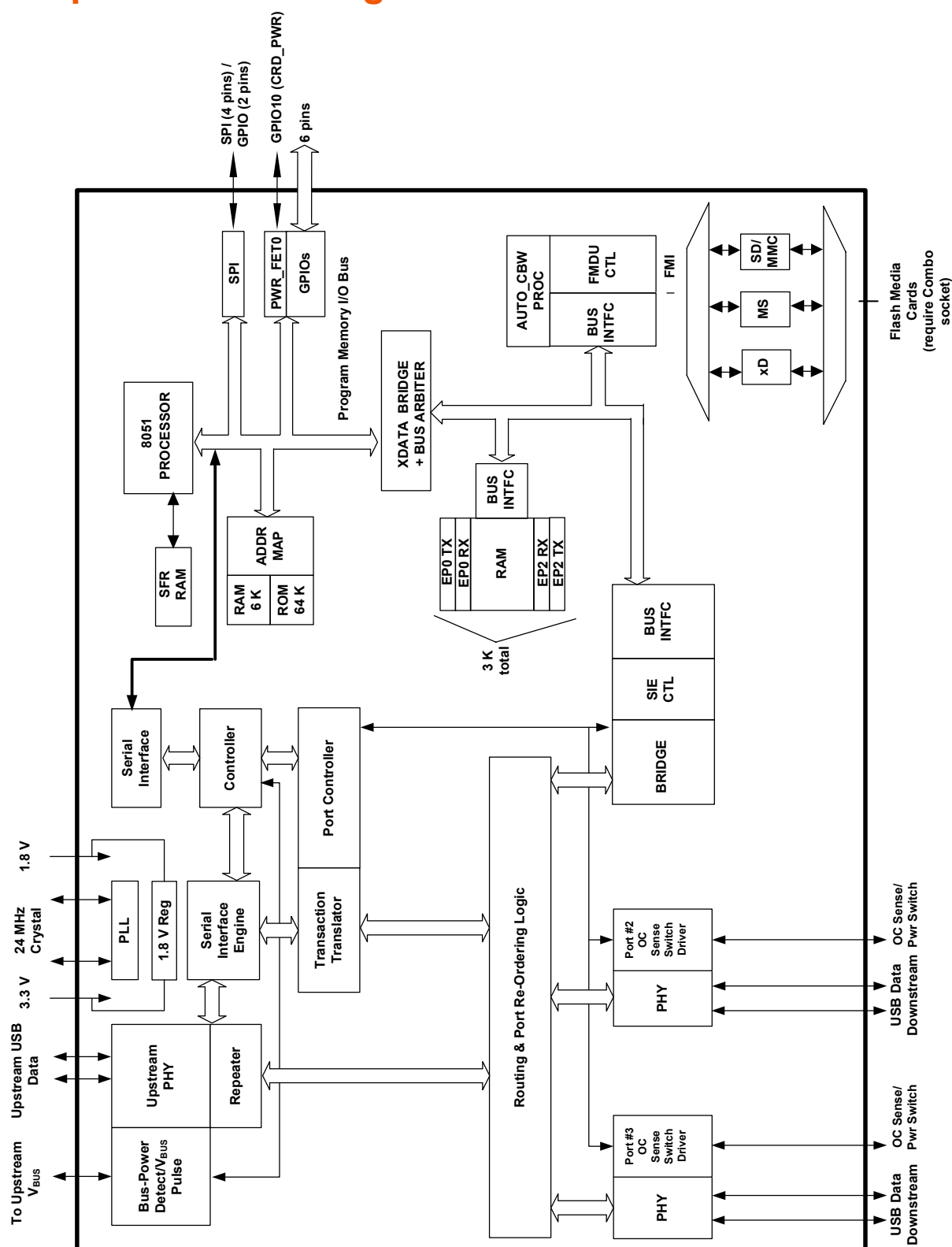


Figure 4.1 USB2640i Block Diagram

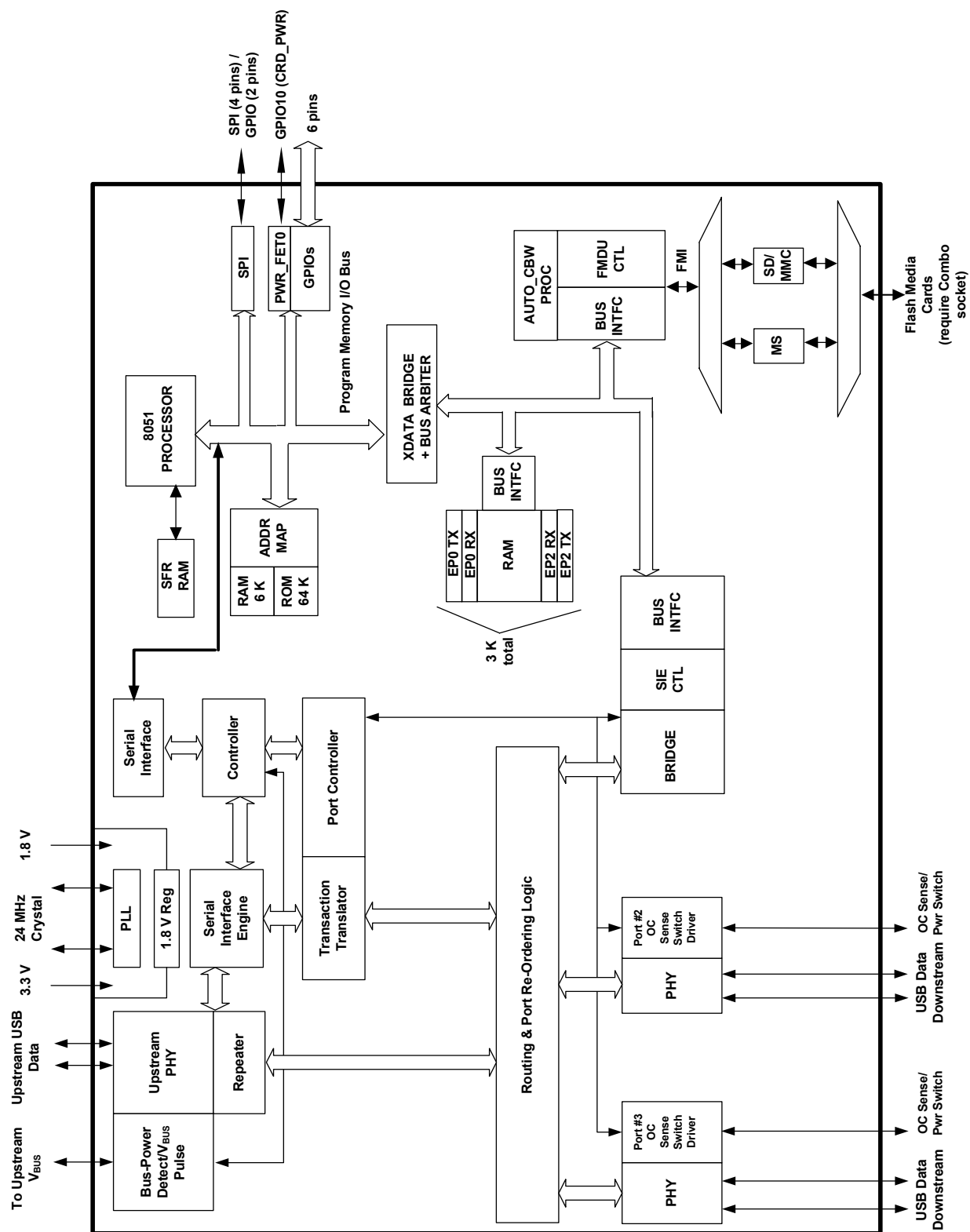


Figure 4.2 USB2641i Block Diagram

Chapter 5 Pin Tables

5.1 48-Pin Tables

Table 5.1 USB2640i 48-Pin Table

xD-PICTURE CARD (Only in USB2640i) / SECURE DIGITAL / MEMORY STICK INTERFACE (18 PINS)			
xD_D3 / SD_D1 / MS_D5	xD_D2 / SD_D0 / MS_D4	xD_D1 / SD_D7 / MS_D6	xD_D0 / SD_D6 / MS_D7
xD_nWP / SD_CLK / MS_BS	xD_ALE / SD_D5 / MS_D1	xD_CLE / SD_CMD / MS_D0	xD_D7 / SD_D4 / MS_D2
xD_D6 / SD_D3 / MS_D3	xD_D5 / SD_D2	xD_nRE	xD_nWE
xD_D4 / GPIO6 / SD_WP / MS_SCLK	xD_nB/R	xD_nCE	GPIO12 / MS_INS
GPIO14 / xD_nCD	GPIO15 / SD_nCD		
USB INTERFACE (5 PINS)			
USB+	USB-	XTAL1 (CLKIN)	XTAL2
RBIAS			
2-PORT USB INTERFACE (7 PINS)			
USBDN_DP2	USBDN_DM2	PRTCTL2	PRTCTL3
USBDN_DP3	USBDN_DM3	VBUS_DET	

Table 5.1 USB2640i 48-Pin Table (continued)

SPI INTERFACE (4 PINS)			
SPI_CE_n	SPI_CLK / GPIO4 / SCL	SPI_DO / GPIO5 / SDA / SPI_SPD_SEL	SPI_DI
MISC (5 PINS)			
nRESET	TEST	GPIO1 / LED / TXD	GPIO2 / RXD
GPIO10 (CRD_PWR)			
POWER AND GROUND (9 PINS)			
(7) VDD33	CRFILT	PLLFILT	
TOTAL 48			

Table 5.2 USB2641i 48-Pin Table

SECURE DIGITAL / MEMORY STICK INTERFACE (14 PINS)			
SD_D1 / MS_D5	SD_D0 / MS_D4	SD_D7 / MS_D6	SD_D6 / MS_D7
SD_CLK / MS_BS	SD_D5 / MS_D1	SD_CMD / MS_D0	SD_D4 / MS_D2
SD_D3 / MS_D3	SD_D2	GPIO12 / MS_INS	GPIO14
GPIO6 / SD_WP / MS_SCLK	GPIO15 / SD_nCD		
USB INTERFACE (5 PINS)			
USB+	USB-	XTAL1 (CLKIN)	XTAL2

Table 5.2 USB2641i 48-Pin Table (continued)

RBIAS			
2-PORT USB INTERFACE (7 PINS)			
USBDN_DP2	USBDN_DM2	PRTCTL2	PRTCTL3
USBDN_DP3	USBDN_DM3	VBUS_DET	
SPI INTERFACE (4 PINS)			
SPI_CE_n	SPI_CLK / GPIO4 / SCL	SPI_DO / GPIO5 / SDA / SPI_SPD_SEL	SPI_DI
MISC (5 PINS)			
nRESET	TEST	GPIO1 / LED / TXD	GPIO2 / RXD
GPIO10 (CRD_PWR)			
POWER AND GROUND (13 PINS)			
(7) VDD33	CRFILT	PLLFILT	PLLFILT
(4) NC			
TOTAL 48			

Chapter 6 Pin Descriptions

This section provides a detailed description of each signal. The signals are arranged in functional groups according to their associated interface. The pin descriptions below are applied when using the internal default firmware and can be referenced in [Chapter 7, "Configuration Options," on page 28](#). Please reference [Chapter 2, Acronyms](#) for a list of the acronyms used.

The “n” symbol in the signal name indicates that the active, or asserted, state occurs when the signal is at a low voltage level. When “n” is not present in the signal name, the signal is asserted at a high voltage level.

The terms assertion and negation are used exclusively. This is done to avoid confusion when working with a mixture of “active low” and “active high” signals. The term assert, or assertion, indicates that a signal is active, independent of whether that level is represented by a high or low voltage. The term negate, or negation, indicates that a signal is inactive.

6.1 USB2640i/USB2641i Pin Descriptions

Table 6.1 USB2640i/USB2641i Pin Descriptions

SYMBOL	48-PIN QFN	BUFFER TYPE (Table 6.2)	DESCRIPTION
xD-PICTURE CARD INTERFACE (APPLIES ONLY TO USB2640i)			
xD_D[7:0]	30 32 33 13 17 18 19 20	I/O12PU	xD-Picture Card Data 7-0 These pins are the bi-directional data signal xD_D7 - xD_D0 and have weak internal pull-up resistors.
xD_ALE	23	O12PD	xD-Picture Card Address Strobe This pin is an active high Address Latch Enable signal for the xD-Picture Card device. This pin has a weak pull-down resistor that is permanently enabled.
xD_nB/R	28	IPU	xD-Picture Card Busy or Data Ready This pin is connected to the BSY/RDY pin of the xD-Picture Card device. When using the internal FET, this pin has an internal weak pull-up resistor that is tied to the output of the internal power FET. If an external FET is used (the internal FET is disabled), then the internal pull-up is not available (an external pull-up is required).

Table 6.1 USB2640i/USB2641i Pin Descriptions (continued)

SYMBOL	48-PIN QFN	BUFFER TYPE (Table 6.2)	DESCRIPTION
xD_nCE	26	O12PU	xD-Picture Card Chip Enable This pin is an active low chip enable signal for the xD-Picture Card device. When using the internal FET, this pin has an internal weak pull-up resistor that is tied to the output of the internal power FET. If an external FET is used (the internal FET is disabled), then the internal pull-up is not available (an external pull-up is required).
xD_CLE	24	O12PD	xD-Picture Card Command Strobe This pin is an active high Command Latch Enable signal for the xD-Picture Card device. This pin has a weak pull-down resistor that is permanently enabled.
GPIO14 /	29	I/O12	This general purpose pin may be used either as input, edge sensitive interrupt input, or output. Custom firmware is required to activate this function.
xD_nCD			xD-Picture Card Detection GPIO This is a GPIO designated by the default firmware as the xD-Picture Card detection pin.
xD_nRE	27	O12PU	xD-Picture Read Enable This pin is an active low read strobe signal for the xD-Picture Card device. When using the internal FET, this pin has an internal weak pull-up resistor that is tied to the output of the internal power FET. If an external FET is used (the internal FET is disabled), then the internal pull-up is not available (an external pull-up is required).
xD_nWE	22	O12PU	xD-Picture Card Write Enable This pin is an active low write strobe signal for the xD-Picture Card device. When using the internal FET, this pin has an internal weak pull-up resistor that is tied to the output of the internal power FET. If an external FET is used (the internal FET is disabled), then the internal pull-up is not available (an external pull-up is required).
xD_nWP	21	O12PD	xD-Picture Card Write Protect This pin is an active low write protect signal for the xD-Picture Card device. This pin has a weak pull-down resistor that is permanently enabled.
MEMORY STICK INTERFACE			
MS_BS	21	O12	Memory Stick Bus State This pin is connected to the bus state pin of the MS device. It is used to control the Bus States 0, 1, 2, and 3 (BS0, BS1, and BS3) of the MS device.

Table 6.1 USB2640i/USB2641i Pin Descriptions (continued)

SYMBOL	48-PIN QFN	BUFFER TYPE (Table 6.2)	DESCRIPTION
GPIO12 / MS_INS	31	I/O12 IPU	This general purpose pin may be used either as input, edge sensitive interrupt input, or output. Custom firmware is required to activate this function. Memory Stick Card Insertion GPIO This is a GPIO designated by the default firmware as the Memory Stick card detection pin and has an internal weak pull-up resistor.
MS_SCLK	13	O12	Memory Stick System Clock This pin is an output clock signal to the MS device.
MS_D[7:0]	20 19 17 18 32 30 23 24	I/O12PD	Memory Stick System Data In/Out These pins are the bi-directional data signals for the MS device. In serial mode, the most significant bit (MSB) of each byte is transmitted first by either MSC or MS device on MS_D0. MS_D0, MS_D2, and MS_D3 have weak pull-down resistors. MS_D1 has a pull down resistor if in parallel mode, otherwise it is disabled. In 4- or 8-bit parallel modes, all MS_D7 - MS_D0 signals have weak pull-down resistors.
SECURE DIGITAL / MULTIMEDIACARD INTERFACE			
SD_D[7:0]	19 20 23 30 32 33 17 18	I/O12PU	Secure Digital Data 7-0 These are the bi-directional data signals SD_D0-SD_D7 and have weak pull-up resistors.
SD_CLK	21	O12	Secure Digital Clock This is an output clock signal to the SD/MMC device.
SD_CMD	24	I/O12PU	Secure Digital Command This is a bi-directional signal that connects to the CMD signal of the SD/MMC device and has an internal weak pull-up resistor.
GPIO6 / SD_WP	13	I/O12	This general purpose pin may be used either as input, edge sensitive interrupt input, or output. Custom firmware is required to activate this function. Secure Digital Write Protected GPIO This is a GPIO designated by the default firmware as the Secure Digital card mechanical write protect detect pin.
GPIO15 / SD_nCD	14	I/O12	This general purpose pin may be used either as input, edge sensitive interrupt input, or output. Custom firmware is required to activate this function. Secure Digital Card Detect GPIO This is a GPIO designated by the default firmware as the Secure Digital card detection pin.

Table 6.1 USB2640i/USB2641i Pin Descriptions (continued)

SYMBOL	48-PIN QFN	BUFFER TYPE (Table 6.2)	DESCRIPTION
USB INTERFACE			
USB- USB+	43 42	I/O-U	USB Bus Data These pins connect to the upstream USB bus data signals. USB+ and USB- can be swapped using the PortSwap feature (See Section 7.3.5.20, "F1h: Port Swap," on page 46).
USBDN_DM [3:2] USBDN_DP [3:2]	3 1 4 2	I/O-U	USB Bus Data These pins connect to the downstream USB bus data signals and can be swapped using the PortSwap feature (See Section 7.3.5.20, "F1h: Port Swap," on page 46).
PRTCTL[3:2]	7 6	I/OD12PU	USB Power Enable As an output, these pins enable power to downstream USB peripheral devices and have weak internal pull-up resistors. See Section 6.3, "Port Power Control" for diagram and usage instructions. As an input, when the power is enabled, these pins monitor the over-current condition. When an over-current condition is detected, the pins turn the power off.
VBUS_DET	39	I	Detect Upstream VBUS Power Detects the state of upstream VBUS power. The Hub monitors VBUS_DET to determine when to assert the internal D+ pull-up resistor (signaling a connect event). When designing a detachable hub, connect this pin to the VBUS power pin of the USB port that is upstream of the Hub. For self-powered applications with a permanently attached host, this pin should be pulled up, typically to VDD33. VBUS is a 3.3 volt input. A resistor divider must be used if connecting to 5 volts of USB power.
RBIAS	47	I-R	USB Transceiver Bias A 12.0 kΩ ±1.0% resistor is attached from VSS to this pin in order to set the transceiver's internal bias currents.
XTAL1 (CLKIN)	45	ICLKx	24 MHz Crystal Input or External clock Input This pin can be connected to one terminal of the crystal or it can be connected to an external 24 MHz 1.8 V clock when a crystal is not used.
XTAL2	44	OCLKx	24 MHz Crystal Output This is the other terminal of the crystal, or it is left open when an external clock source is used to drive XTAL1(CLKIN).

Table 6.1 USB2640i/USB2641i Pin Descriptions (continued)

SYMBOL	48-PIN QFN	BUFFER TYPE (Table 6.2)	DESCRIPTION
SPI INTERFACE			
SPI_CE_n	8	O12	SPI Chip Enable This is the active low chip enable output. When the SPI interface is enabled, drive this pin high in power down states.
SPI_CLK /	9	I/O12	SPI Clock This is the SPI clock out to the serial ROM. See Section 6.4, "ROM BOOT Sequence" for diagram and usage instructions. During reset, drive this pin low.
GPIO4 /			This pin may be used either as input, edge sensitive interrupt input, or output. Custom firmware is required to activate this function.
SCL			When configured, this is the I²C EEPROM clock pin.
SPI_DO /	10	I/O12	SPI Data Out This is the data out for the SPI port. See Section 6.4, "ROM BOOT Sequence" for diagram and usage instructions.
GPIO5 /			This pin may be used either as input, edge sensitive interrupt input, or output. Custom firmware is required to activate this function.
SDA /			This pin is the data pin when the device is connected to the optional I²C EEPROM.
SPI_SPD_SEL			This pin is used to select the speed of the SPI interface. During nRESET assertion, this pin will be tri-stated with the weak pull-down resistor enabled. When nRESET is negated, the value on the pin will be internally latched, and the pin will revert to SPI_DO functionality, the internal pull-down will be disabled. '0' = 30 MHz (No external resistor should be applied) '1' = 60 MHz (A 10 K external pull-up resistor must be applied) If the latched value is '1', then the pin is tri-stated when the chip is in the suspend state. If the latched value is '0', then the pin is driven low during a suspend state.
SPI_DI	11	I/O12PD	SPI Data In This is the data in to the controller from the ROM. This pin has a weak internal pull-down applied at all times to prevent floating.
MISC			
GPIO1 /	37	I/O12	This pin may be used either as input, edge sensitive interrupt input, or output. Custom firmware is required to activate this function.
LED /			GPIO1 can be used as an LED output.
TXD			The signal can be used as input to the TxD of UART in the device. Custom firmware is required to activate this function.

Table 6.1 USB2640i/USB2641i Pin Descriptions (continued)

SYMBOL	48-PIN QFN	BUFFER TYPE (Table 6.2)	DESCRIPTION
GPIO2 / RXD	36	I/O12	This pin may be used either as input, edge sensitive interrupt input, or output. Custom firmware is required to activate this function. This signal can be used as input to the RXD of the internal UART. Custom firmware is required to activate this function.
GPIO10 (CRD_PWR)	35	I/O200	Card power drive: 3.3 V (100 mA or 200 mA) This pin powers the multiplexed flash media interface (slot) for xD, MS, and SD/MMC. If card power is not being used to power the multiplexed flash media interface, this pin may be used as a GPIO. It is a requirement for this to be the only FET used to power xD-Picture Card devices. Failure to do this will violate xD voltage specification on xD-Picture Card device pins. Bits 0, 1, 2, and 3 control FET 2 of Register A5h. Please reference Section 7.3.4.5, "A8h: LED Blink Interval (1 byte)," on page 38.
nRESET	38	IS	RESET Input The system uses this active low signal to reset the chip. The active low pulse should be at least 1 μs wide.
TEST	40	I	TEST Input Tie this pin to ground for normal operation.
NC	22 26 27 28		No Connects No connect pins only apply to the USB2641i. No trace or signal should be routed or attached to these pins.
DIGITAL / POWER / GROUND			
CRFILT	15		VDD Core Regulator Filter Capacitor This pin must have a 1.0 μF (or greater) $\pm 20\%$ (ESR $< 0.1 \Omega$) capacitor to VSS.
VDD33	5 12 16 25 34 41 48		3.3 V Power and Voltage Regulator Inputs Please refer to Chapter 10, "DC Parameters," on page 58 for more information. Pins 16 and 48 each require an external bypass capacitor of 4.7 μF minimum.
PLLFILT	46		PLL Regulator Filter Capacitor This pin must have a 1.0 μF (or greater) $\pm 20\%$ (ESR $< 0.1 \Omega$) capacitor to VSS.
VSS	ePad		The ground pad / ePad is the only VSS for the device and must be tied to ground with multiple vias.

6.2 Buffer Type Descriptions

Table 6.2 USB2640i/USB2641i Buffer Type Descriptions

BUFFER	DESCRIPTION
I	Input.
IPU	Input, weak internal pull-up.
IS	Input with Schmitt trigger.
I/O12	Input/output buffer with 12 mA sink and 12 mA source.
I/O200	Input/output buffer 12 mA with FET disabled, 100/200 mA source only when the FET is enabled.
I/O12PD	Input/output buffer with 12 mA sink and 12 mA source, with an internal weak pull-down resistor.
I/O12PU	Open drain, 12 mA sink with pull-up. Input with Schmitt trigger.
I/OD12PU	Input/open drain output buffer with a 12 mA sink.
O12	Output buffer with a 12 mA sink and a 12 mA source.
O12PD	Output buffer with 12 mA sink and 12 mA source, with a pull-down resistor.
O12PU	Output buffer with 12 mA sink and 12 mA source, with a pull-up resistor.
ICLKx	XTAL clock input.
OCLKx	XTAL clock output.
I/O-U	Analog input/output as defined in the USB 2.0 Specification.
I-R	RBIAS.

6.3 Port Power Control

Port Power Control Using USB Power Switch

The USB2640i/USB2641i has a single port power control and over-current sense signal for each downstream port. When disabling port power, the driver will actively drive a '0'. To avoid unnecessary power dissipation, the internal pull-up resistor will be disabled at that time. When port power is enabled, the output driver is disabled, and the pull-up resistor is enabled creating an open drain output. If there is an over-current situation, the USB Power Switch will assert the open drain OCS signal. The Schmitt trigger input will detect this event as a low. The open drain output does not interfere. The internal over-current sense filter handles the transient conditions, such as low voltage, while the device is powering up.

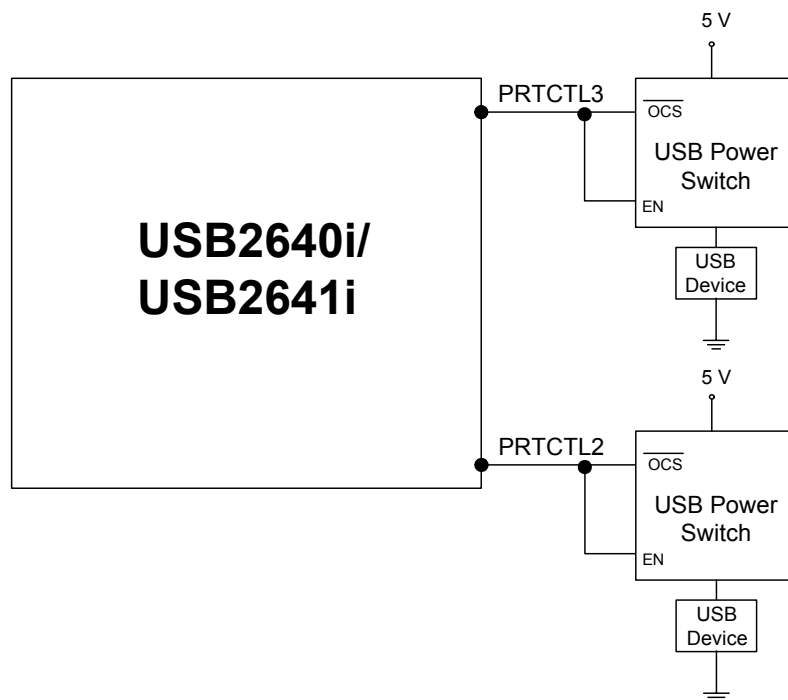


Figure 6.1 Port Power Control with USB Power Switch

Port Power Control Using a Poly Fuse

When using the USB2640i/USB2641i with a poly fuse, an external diode must be used (See [Figure 6.2](#)). When disabling port power, the USB2640i/USB2641i will drive a '0'. This procedure will have no effect since the external diode will isolate the pin from the load. When port power is enabled, the USB2640i/USB2641i output driver is disabled, and the pull-up resistor is enabled which creates an open drain output. The open drain output condition means that the pull-up resistor is providing 3.3 volts to the anode of the diode. If there is an over-current situation, the poly fuse will open causing the cathode of the diode to go to 0 volts. The anode of the diode will be at 0.7 volt, and the Schmitt trigger input will register this as a low resulting in an over-current detection. The open drain output does not interfere.

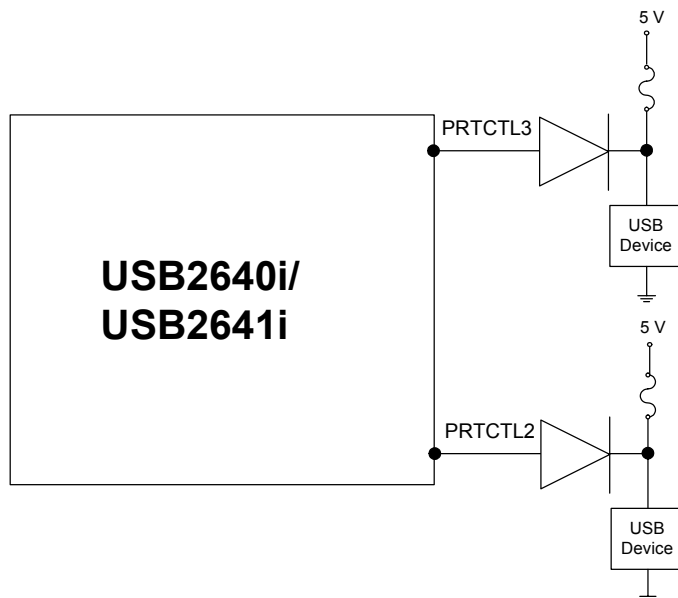


Figure 6.2 Port Power control with Poly Fuse

When using a single poly fuse to power all devices, note that for the ganged situation, all power control pins must be tied together.

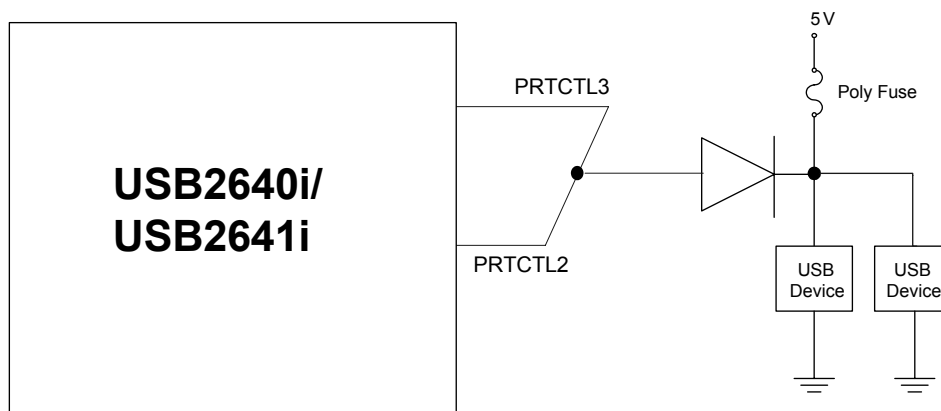


Figure 6.3 Port Power with Ganged Control with Poly Fuse

6.4 ROM BOOT Sequence

After power-on reset, the internal firmware checks for an external SPI flash device that contains a valid signature of "2DFU" (device firmware upgrade) beginning at address 0xFFFF. If a valid signature is found, then the external ROM is enabled and code execution begins at address 0x0000 in the external SPI device. Otherwise, code execution continues from the internal ROM.

If there is no SPI ROM detected, the internal firmware then checks for the presence of an I²C ROM. The firmware looks for the signature 'ATA2' at the offset of 0xFC-0xFF in the I²C ROM. The firmware reads in the I²C ROM to configure the hardware and software internally. Please refer to section [7.3.2 EEPROM Data Descriptor on page 29](#) for the details of the configuration options.

The SPI ROM required for the USB2640i/USB2641i must be 1 Mbit and support either 30 MHz or 60 MHz. The frequency used is set using the SPI_SPD_SEL. For 30 MHz operation, this pin must be pulled to ground through a 100 k Ω resistor. For 60 MHz operation, this pin must be pulled up through a 100 k Ω resistor. SPI_SPD_SEL: This pin is used to choose the speed of the SPI interface. During nRESET assertion, this pin will be tri-stated with the weak pull-down resistor enabled. When nRESET is negated, the value on the pin will be internally latched, and the pin will revert to SPI_DO functionality, the internal pull-down will be disabled.

The firmware can determine the speed of operation on the SPI port by checking the SPI_SPEED in the SPI_CTL register (0x2400 - RESET = 0x02). Both 1- and 2-bit SPI operation is supported. For optimum throughput, a 2-bit SPI ROM is recommended. Both mode 0 and mode 3 SPI ROMs are also supported.

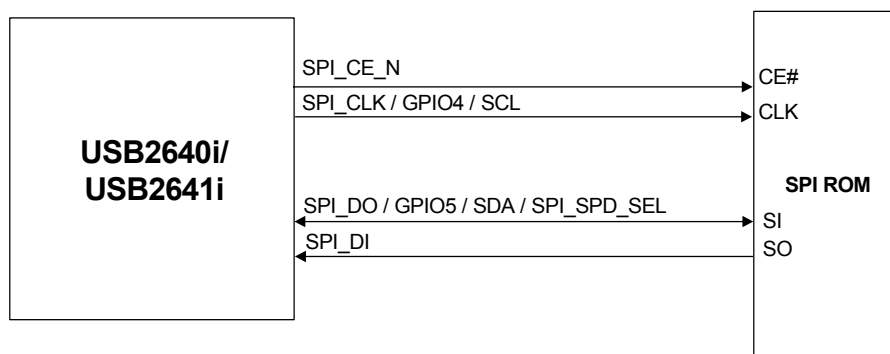


Figure 6.4 USB2640i/USB2641i SPI ROM Connection

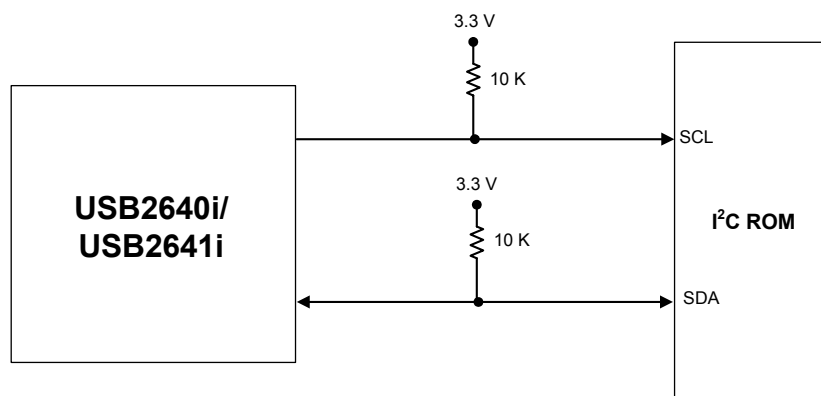


Figure 6.5 USB2640i/USB2641i I²C Connection

Chapter 7 Configuration Options

7.1 Hub

SMSC's USB 2.0 hub is fully compliant to the Universal Serial Bus Specification available from the USB Implementer's Forum found at <http://www.usb.org> (Revision 2.0 April 27, 2000 and the 12/7/2000 and 5/28/2002 Errata). Please reference Chapter 11 (Hub Specification) for general details regarding hub operation and functionality.

The hub provides 1 transaction translator (TT) that is shared by both downstream ports (defined as a single-TT configuration). The TT contains 4 non-periodic buffers.

7.1.1 Hub Configuration Options

The SMSC hub supports a large number of features (some are mutually exclusive), and must be configured in order to correctly function when attached to a USB host controller. There are two principal ways to configure the hub:

- via the internal default settings or
- by settings stored in an external EEPROM or SPI Flash device.

7.1.1.1 Power Switching Polarity

The hub only supports active high port power controllers.

7.1.2 VBus Detect

According to Section 7.2.1 of the USB 2.0 Specification, a downstream port cannot provide power to its D+ or D- pull-up resistors unless the upstream port's VBUS is in the asserted (powered) state. The VBUS_DET pin on the hub monitors the state of the upstream VBUS signal and will not pull-up the D+ resistor if VBUS is not active. If VBUS goes from an active to an inactive state (not powered), the hub will remove power from the D+ pull-up resistor within 10 seconds.

7.2 Card Reader

The SMSC USB2640i/USB2641i is fully compliant with the following flash media card reader specifications:

- Secure Digital 2.0 / MultiMediaCard 4.2
 - SD 2.0, HS-SD, HC-SD
 - TransFlash™ and reduced form factor media
 - 1/4/8 bit MMC 4.2
- Memory Stick 1.43
- Memory Stick Pro Format 1.02
- Memory Stick Pro-HG Duo Format 1.01
 - Memory Stick, MS Duo, HS-MS, MS Pro-HG, MS Pro
- Memory Stick Duo 1.10
- xD-Picture Card 1.2 compliant

7.3 System Configurations

7.3.1 EEPROM/SPI Interface

The USB2640i/USB2641i can be configured via a 2-wire (I²C) EEPROM (256x8 or a recommended 512x8 for internal ROM support) or an external SPI ROM flash device containing the firmware for the USB2640i/USB2641i. If an external configuration device does not exist, the internal default values will be used. If one of the external devices is used for configuration, the OEM can update the values through the USB interface. The hub will then “attach” to the upstream USB host.

When using an external SPI Flash, the register addresses in the following three tables (Table 7.1, Table 7.2,) refer to offsets from the starting location ‘FE80h’.

The USBDM tool set is available in the USB264x Hub Card reader combo software release package. To download the software package from SMSC’s website, please visit:

https://www2.smsc.com/mkt/CW_SFT_PUB.nsf/Agreements/OBJ+Hub+Card+Reader

to go to the OBJ Hub Card Reader Software Download Agreement. Review the license, and if you agree, check the “I agree” box and then select “Confirm”. You will then be able to download the USB264x Hub Card reader combo release package zip file containing the USBDM tool set.

Please note that the following applies to the system values and descriptions when used:

- N/A = Not applicable to this part
- Reserved = For internal use

7.3.2 EEPROM Data Descriptor

Table 7.1 Internal Flash Media Controller Configurations

ADDRESS	REGISTER NAME	DESCRIPTION	DEFAULT VALUE
00h	USB_SER_LEN	USB Serial String Descriptor Length	1Ah
01h	USB_SER_TYP	USB Serial String Descriptor Type	03h
02h-19h	USB_SER_NUM	USB Serial Number	"000000264001" (See Note 7.1)
1Ah-1Bh	USB_VID	USB Vendor Identifier	0424
1Ch-1Dh	USB_PID	USB Product Identifier	4050
1Eh	USB_LANG_LEN	USB Language String Descriptor Length	04h
1Fh	USB_LANG_TYP	USB Language String Descriptor Type	03h
20h	USB_LANG_ID_LSB	USB Language Identifier Least Significant Byte	09h (See Note 7.3)
21h	USB_LANG_ID_MSB	USB Language Identifier Most Significant Byte	04h (See Note 7.3)
22h	USB_MFR_STR_LEN	USB Manufacturer String Descriptor Length	10h
23h	USB_MFR_STR_TYP	USB Manufacturer String Descriptor Type	03h
24h-31h	USB_MFR_STR	USB Manufacturer String	“Generic” (See Note 7.1)

Table 7.1 Internal Flash Media Controller Configurations (continued)

ADDRESS	REGISTER NAME	DESCRIPTION	DEFAULT VALUE
32h-5Dh	Reserved	-	00h
5Eh	USB_PRD_STR_LEN	USB Product String Descriptor Length	30h
5Fh	USB_PRD_STR_TYP	USB Product String Descriptor Type	03h
60h-99h	USB_PRD_STR	USB Product String	"Ultra Fast Media Reader" (See Note 7.1)
9Ah	USB_BM_ATT	USB BmAttribute	80h
9Bh	USB_MAX_PWR	USB Max Power	30h (96 mA)
9Ch	ATT_LB	Attribute Lo byte	40h (Reverse SD_WP only)
9Dh	ATT_HLB	Attribute Hi Lo byte	00h
9Eh	ATT_LHB	Attribute Lo Hi byte	00h
9Fh	ATT_HB	Attribute Hi byte	00h
A0h	MS_PWR_LB	Memory Stick Device Power Lo byte	08h
A1h	MS_PWR_HB	Memory Stick Device Power Hi byte	00h
A2h	Not Applicable	-	80h
A3h	Not Applicable	-	00h
A4h	SM_PWR_LB	Smart Media Device Power Lo byte	00h (See Note 7.2)
A5h	SM_PWR_HB	Smart Media Device Power Hi byte	08h (See Note 7.2)
A6h	SD_PWR_LB	Secure Digital Device Power Lo byte	00h
A7h	SD_PWR_HB	Secure Digital Device Power Hi byte	80h
A8h	LED_BLK_INT	LED Blink Interval	02h
A9h	LED_BLK_DUR	LED Blink After Access	28h
AAh - B0h	DEV0_ID_STR	Device 0 Identifier String	"COMBO"
B1h - B7h	DEV1_ID_STR	Device 1 Identifier String	N/A
B8h - BEh	DEV2_ID_STR	Device 2 Identifier String	N/A
BFh - C5h	DEV3_ID_STR	Device 3 Identifier String	N/A
C6h - CDh	INQ_VEN_STR	Inquiry Vendor String	"Generic"
CEh - D2h	INQ_PRD_STR	Inquiry Product String	2640
D3h	DYN_NUM_LUN	Dynamic Number of LUNs	FFh
D4h - D7h	LUN_DEV_MAP	Device to LUN Mapping	FFh, FFh, FFh, FFh

Table 7.1 Internal Flash Media Controller Configurations (continued)

ADDRESS	REGISTER NAME	DESCRIPTION	DEFAULT VALUE
D8h - DAh	Reserved	-	00h, 04h, 09h
DBh - DDh	Reserved	-	5Ch, 59h, 9Ah

Table 7.2 Hub Controller Configurations

ADDRESS	REGISTER NAME	DESCRIPTION	DEFAULT VALUE
DEh	VID_LSB	Vendor ID Least Significant Byte	24h
DFh	VID_MSB	Vendor ID Most Significant Byte	04h
E0h	PID_LSB	Product ID Least Significant Byte	40h
E1h	PID_MSB	Product ID Most Significant Byte	26h
E2h	DID_LSB	Device ID Least Significant Byte	00h
E3h	DID_MSB	Device ID Most Significant Byte	00h
E4h	CFG_DAT_BYT1	Configuration Data Byte 1	8Bh
E5h	CFG_DAT_BYT2	Configuration Data Byte 2	28h
E6h	CFG_DAT_BYT3	Configuration Data Byte 3	00h
E7h	NR_DEVICE	Non-Removable Devices	02h
E8h	PORT_DIS_SP	Port Disable (Self)	00h
E9h	PORT_DIS_BP	Port Disable (Bus)	00h
EAh	MAX_PWR_SP	Max Power (Self)	01h
EBh	MAX_PWR_BP	Max Power (Bus)	32h
ECh	HC_MAX_C_SP	Hub Controller Max Current (Self)	01h
EDh	HC_MAX_C_BP	Hub Controller Max Current (Bus)	32h
EEh	PWR_ON_TIME	Power-on Time	32h
EFh	BOOST_UP	Boost_Up	00h
F0h	BOOST_3:0	Boost_3:0	00h
F1h	PRT_SWP	Port Swap	00h
F2h	PRTM12	Port Map 12	00h
F3h	PRTM3	Port Map 3	00h

Table 7.3 Other Internal Configurations

ADDRESS	REGISTER NAME	DESCRIPTION	DEFAULT VALUE
F4h	Reserved	-	00h
F5h	Reserved	-	66h
F6-FBh	Reserved	-	00h

Table 7.3 Other Internal Configurations

ADDRESS	REGISTER NAME	DESCRIPTION	DEFAULT VALUE
FCh-FFh	NVSTORE_SIG	Non-volatile storage signature ("ATA2")	"ATA2"

Note 7.1 This value is a UNICODE UTF-16LE encoded string value that meets the USB 2.0 Specification (Revision 2.0, 2000). Values in double quotations without this note are ASCII values.

Note 7.2 A value of "SM" will be overridden with "xD" once an xD-Picture Card has been identified.

Note 7.3 For a list of the most current 16-bit language ID's defined by the USB-IF, please visit <http://www.unicode.org> or consult *The Unicode Standard, Worldwide Character Encoding*, (Version 4.0), The Unicode Consortium, Addison-Wesley Publishing Company, Reading, Massachusetts.

7.3.3 EEPROM Data Descriptor Register Descriptions

7.3.3.1 00h: USB Serial String Descriptor Length

BYTE	NAME	DESCRIPTION
0	USB_SER_LEN	USB serial string descriptor length as defined by Section 9.6.7 "String" of the USB 2.0 Specification (Revision 2.0, 2000). This field is the "bLength" which describes the size of the string descriptor (in bytes).

7.3.3.2 01h: USB Serial String Descriptor Type

BYTE	NAME	DESCRIPTION
1	USB_SER_TYP	USB serial string descriptor type as defined by Section 9.6.7 "String" of the USB 2.0 Specification (Revision 2.0, 2000). This field is the "bDescriptorType" which is a constant value associated with a string descriptor type.

7.3.3.3 02h-19h: USB Serial Number Option

BYTE	NAME	DESCRIPTION
25:2	USB_SER_NUM	Maximum string length is 12 hex digits. Must be unique to each device.

7.3.3.4 1Ah-1Bh: USB Vendor Identifier Option

BYTE	NAME	DESCRIPTION
1:0	USB_VID	This ID is unique for every vendor. The vendor ID is assigned by the USB Implementer's Forum.

7.3.3.5 1Ch-1Dh: USB Product Identifier Option

BYTE	NAME	DESCRIPTION
1:0	USB_PID	This ID is unique for every product. The product ID is assigned by the vendor.

7.3.3.6 1Eh: USB Language String Descriptor Length

BYTE	NAME	DESCRIPTION
0	USB_LANG_LEN	USB serial string descriptor length as defined by Section 9.6.7 “String” of the USB 2.0 Specification (Revision 2.0, 2000). This field is the “bLength” which describes the size of the string descriptor (in bytes).

7.3.3.7 1Fh: USB Language String Descriptor Type

BYTE	NAME	DESCRIPTION
1	USB_LANG_TYP	USB serial string descriptor type as defined by Section 9.6.7 “String” of the USB 2.0 Specification (Revision 2.0, 2000). This field is the “bDescriptorType” which is a constant value associated with a string descriptor type.

7.3.3.8 20h: USB Language Identifier Least Significant Byte

BYTE	NAME	DESCRIPTION
2	USB_LANG_ID_LSB	English Language Code = ‘0409’. See Note 7.3 to reference additional language ID’s defined by the USB-IF.

7.3.3.9 21h: USB Language Identifier Most Significant Byte

BYTE	NAME	DESCRIPTION
3	USB_LANG_ID_MSB	English Language Code = ‘0409’. See Note 7.3 to reference additional language ID’s defined by the USB-IF.

7.3.3.10 22h: USB Manufacturer String Descriptor Length

BYTE	NAME	DESCRIPTION
0	USB_MFR_STR_LEN	USB serial string descriptor length as defined by Section 9.6.7 “String” of the USB 2.0 Specification (Revision 2.0, 2000). This field is the “bLength” which describes the size of the string descriptor (in bytes).

7.3.3.11 23h: USB Manufacturer String Descriptor Type

BYTE	NAME	DESCRIPTION
1	USB_MFR_STR_TYP	USB serial string descriptor type as defined by Section 9.6.7 “String” of the USB 2.0 Specification (Revision 2.0, 2000). This field is the “bDescriptorType” which is a constant value associated with a string descriptor type.

7.3.3.12 24h-31h: USB Manufacturer String

BYTE	NAME	DESCRIPTION
15:2	USB_MFR_STR	Maximum string length is 28 characters. (See Note 7.4)

7.3.3.13 32h-5Dh: Reserved

BYTE	NAME	DESCRIPTION
59:16	Reserved	Reserved.

7.3.3.14 5Eh: USB Product String Descriptor Length

BYTE	NAME	DESCRIPTION
0	USB_PRD_STR	USB serial string descriptor length as defined by Section 9.6.7 “String” of the USB 2.0 Specification (Revision 2.0, 2000). This field is the “bLength” which describes the size of the string descriptor (in bytes).

7.3.3.15 5Fh: USB Product String Descriptor Type

BYTE	NAME	DESCRIPTION
1	USB_PRD_STR	USB serial string descriptor type as defined by Section 9.6.7 “String” of the USB 2.0 Specification (Revision 2.0, 2000). This field is the “bDescriptorType” which is a constant value associated with a string descriptor type.

7.3.3.16 60h-99h: USB Product String

BYTE	NAME	DESCRIPTION
59:2	USB_PRD_STR	This string will be used during the USB enumeration process in the Windows operating system. Maximum string length is 28 characters. (See Note 7.4)

Note 7.4 While the full strings are reported during USB enumeration, Windows XP/Vista reads concatenated version of the strings from the standard SCSI inquiry response when storing the values for display in the Windows registry and device manager.

7.3.3.17 9Ah: USB BmAttribute (1 byte)

BIT	NAME	DESCRIPTION
7:0	USB_BM_ATT	Self- or Bus-Power: Selects between self- and bus-powered operation. The hub is either self-powered (draws less than 2 mA of upstream bus power) or bus-powered (limited to a 100 mA maximum of upstream power prior to being configured by the host controller). When configured as a bus-powered device, the SMSC hub consumes less than 100 mA of current prior to being configured. After configuration, the bus-powered SMSC hub (along with all associated hub circuitry, any embedded devices if part of a Compound Device, and 100 mA per externally available downstream port) must consume no more than 500 mA of upstream VBUS current. The current consumption is system dependent, and the OEM must ensure that the USB 2.0 Specification is not violated. When configured as a self-powered device, <1 mA of upstream VBUS current is consumed and all ports are available, with each port being capable of sourcing 500 mA of current. 80 = Bus-powered operation (default) C0 = Self-powered operation A0 = Bus-powered operation with remote wake-up E0 = Self-powered operation with remote wake-up

7.3.3.18 9Bh: USB MaxPower (1 byte)

BIT	NAME	DESCRIPTION
7:0	USB_MAX_PWR	USB Max Power per the USB 2.0 Specification. Do NOT set this value greater than 100 mA.

7.3.3.19 9Ch-9Fh: Attribute Byte Descriptions

BYTE	BYTE NAME	BIT	DESCRIPTION
0	ATT_LB	3:0	Always reads '0'.
		4	Inquire Manufacturer and Product ID Strings '1' - Use the Inquiry Manufacturer and Product ID Strings. '0' (default) - Use the USB Descriptor Manufacturer and Product ID Strings.
		5	Always reads '0'.
		6	Reverse SD Card Write Protect Sense '1' (default) - SD cards will be write protected when SW_nWP is high, and writable when SW_nWP is low. '0' - SD cards will be write protected when SW_nWP is low, and writable when SW_nWP is high.
		7	Reserved

BYTE	BYTE NAME	BIT	DESCRIPTION
1	ATT_HLB	3:0	Always reads '0'.
		4	Activity LED True polarity '1' - Activity LED to Low True. '0' (default) - Activity LED polarity to High True.
		5	Common Media Insert / Media Activity LED '1' - The activity LED will function as a common media inserted/media access LED. '0' (default) - The activity LED will remain in its idle state until media is accessed.
		7:6	Always reads '0'.
2	ATT_LHB	0	Attach on Card Insert / Detach on Card Removal '1' - Attach on Insert is enabled. '0' (default) - Attach on Insert is disabled.
		1	Always reads '0'.
		2	Enable Device Power Configuration '1' - Custom Device Power Configuration stored in the NVSTORE is used. '0' (default) - Default Device Power Configuration is used.
		7:3	Always reads '0'.
3	ATT_HB	6:0	Always reads '0'.
		7	xD Player Mode

7.3.4 A0h-A7h: Device Power Configuration

The USB4640/USB4640i has one internal FET which can be utilized for card power. This section describes the internal default configuration. The settings are stored in NVSTORE and provide the following features:

1. A card can be powered by an external FET or by an internal FET.
2. The power limit can be set to 100 mA or 200 mA (Default) for the internal FET.

Each media uses two bytes to store its device power configuration. Bit 3 selects between internal or external card power FET options. For internal FET card power control, bits 0 through 2 are used to set the power limit. The "Device Power Configuration" bits are ignored unless the "Enable Device Power Configuration" bit is set. See [Section 7.3.3.19, "9Ch-9Fh: Attribute Byte Descriptions," on page 35](#).

7.3.4.1 A0h-A1h: Memory Stick Device Power

FET	TYPE	BITS	BIT TYPE	DESCRIPTION
0	FET Lo Byte MS_PWR_LB	3:0	Low Nibble	0000b Disabled
1		7:4	High Nibble	
2	FET Hi Byte MS_PWR_HB	3:0	Low Nibble	0000b Disabled 0001b External FET enabled 1000b Internal FET with 100 mA power limit 1010b Internal FET with 200 mA power limit
3		7:4	High Nibble	0000b Disabled

7.3.4.2 A2h-A3h: Not Applicable

BYTE	NAME	DESCRIPTION
1:0	Not Applicable	Not applicable to USB2640i/USB2641i.

7.3.4.3 A4h-A5h: Smart Media Device Power

FET	TYPE	BITS	BIT TYPE	DESCRIPTION
0	FET Lo Byte SM_PWR_LB	3:0	Low Nibble	0000b Disabled
1		7:4	High Nibble	
2	FET Hi Byte SM_PWR_HB	3:0	Low Nibble	0000b Disabled 0001b External FET enabled 1000b Internal FET with 100 mA power limit 1010b Internal FET with 200 mA power limit
3		7:4	High Nibble	0000b Disabled

7.3.4.4 A6h-A7h: Secure Digital/MultiMediaCard Device Power

FET	TYPE	BITS	BIT TYPE	DESCRIPTION
0	FET Lo Byte SD_PWR_LB	3:0	Low Nibble	0000b Disabled
1		7:4	High Nibble	
2	FET Hi Byte SD_PWR_HB	3:0	Low Nibble	0000b Disabled 0001b External FET enabled 1000b Internal FET with 100 mA power limit 1010b Internal FET with 200 mA power limit
3		7:4	High Nibble	0000b Disabled

7.3.4.5 A8h: LED Blink Interval (1 byte)

BYTE	NAME	DESCRIPTION
0	LED_BLK_INT	The blink rate is programmable in 50 ms intervals. Bit 7 indicates an idle state: '0' - Off '1' - On Bits 0-6 are used to determine the blink interval up to a max of 128 x 50 ms.

7.3.4.6 A9h: LED Blink Duration (1 byte)

BYTE	NAME	DESCRIPTION
1	LED_BLK_DUR	LED blink After Access. This byte is used to designate the number of seconds that the GPIO 1 LED will continue to blink after a drive access. Setting this byte to "05" will cause the GPIO 1 LED to blink for 5 seconds after a drive access.

7.3.4.7 AAh-B0h: Device 0 Identifier String

BYTE	NAME	STRING	DESCRIPTION
6:0	DEV0_ID_STR	"COMBO"	MS, SM, and SD/MMC are mapped to device 0 identifier string because USB2640i/USB2641i only supports one LUN. When applicable, the "SM" value will be overridden with xD once an xD-Picture Card has been identified.

7.3.4.8 B1h-C5h: Not Applicable

BYTE	NAME	DESCRIPTION
20:0	Not Applicable	Not applicable to USB2640i/USB2641i.

7.3.4.9 C6h-CDh: Inquiry Vendor String

BYTE	NAME	STRING	DESCRIPTION
7:0	INQ_VEN_STR	"Generic"	If bit 4 of the 1st attribute byte is set, the device will use these strings in response to a USB inquiry command, instead of the USB Descriptor Manufacturer and Product ID Strings.

7.3.4.10 CEh-D2h: Inquiry Product String

BYTE	NAME	UINT	DESCRIPTION
4:0	INQ_PRD_STR	2640	If bit 4 of the 1st attribute byte is set, the device will use these strings in response to a USB inquiry command, instead of the USB Descriptor Manufacturer and Product ID Strings.

7.3.4.11 D3h: Dynamic Number of LUNs

BIT	BYTE NAME	UCHAR	DESCRIPTION
7:0	DYN_NUM_LUN	FFh	These bytes are used to specify the number of LUNs the device exposes to the host. These bytes are also used for icon sharing by assigning more than one LUN to a single icon. This is used in applications where the device utilizes a combo socket and the OEM wishes to have only a single icon displayed for one or more interfaces. USB2640i/USB2641i supports one LUN. MS, SM, and SD/MMC are mapped to that LUN. If this field is set to "FF", the program assumes that you are using the default value of "04" and will display icons for xD, MS, and SD/MMC. If this field is any other value besides "FF", you must specify the LUN# assignments in the boxes starting with LUN 00 and going to (# of Icons to Display -1). These bytes are reserved for internal use only.

7.3.4.12 D4h-D7h: Device to LUN Mapping

BYTE	NAME	UCHARS	DESCRIPTION
3:0	DEV_LUN_MAP	FFh, FFh, FFh, FFh	These bytes are used to specify the number of LUNs the device exposes to the host. These bytes are also used for icon sharing by assigning more than one LUN to a single icon. This is used in applications where the device utilizes a combo socket and the OEM wishes to have only a single icon displayed for one or more interfaces. USB2640i/USB2641i supports one LUN. MS, SM, and SD/MMC are mapped to that LUN. If this field is set to "FF", the program assumes that you are using the default value of "04" and will display icons for xD, MS, and SD/MMC. If this field is any other value besides "FF", you must specify the LUN# assignments in the boxes starting with LUN 00 and going to (# of Icons to Display -1). These bytes are reserved for internal use only.

7.3.4.13 D8h-DDh: Reserved

BYTE	BYTE NAME	DESCRIPTION
5:0	Reserved	For internal use only.

7.3.5 Hub Controller Configurations

7.3.5.1 DEh: Vendor ID (LSB)

BIT	BYTE NAME	DESCRIPTION
7:0	VID_LSB	Least Significant Byte of the Vendor ID. This is a 16-bit value that uniquely identifies the Vendor of the user device (assigned by USB Implementer's Forum).

7.3.5.2 DFh: Vendor ID (MSB)

BIT	BYTE NAME	DESCRIPTION
7:0	VID_MSB	Most Significant Byte of the Vendor ID. This is a 16-bit value that uniquely identifies the Vendor of the user device (assigned by USB Implementer's Forum).

7.3.5.3 E0h: Product ID (LSB)

BIT	NAME	DESCRIPTION
7:0	PID_LSB	Least Significant Byte of the Product ID. This is a 16-bit value that the vendor can assign that uniquely identifies this particular product.

7.3.5.4 E1h: Product ID (MSB)

BIT	NAME	DESCRIPTION
7:0	PID_MSB	Most Significant Byte of the Product ID. This is a 16-bit value that the vendor can assign that uniquely identifies this particular product.

7.3.5.5 E2h: Device ID (LSB)

BIT	NAME	DESCRIPTION
7:0	DID_LSB	Least Significant Byte of the Device ID. This is a 16-bit device release number in BCD (binary coded decimal) format.

7.3.5.6 E3h: Device ID (MSB)

BIT	NAME	DESCRIPTION
7:0	DID_MSB	Most Significant Byte of the Device ID. This is a 16-bit device release number in binary coded decimal (BCD) format.

7.3.5.7 E4h: Configuration Data Byte 1 (CFG_DAT_BYT1)

BIT	NAME	DESCRIPTION
7	SELF_BUS_PWR	Self- or Bus-Power: Selects between self- and bus-powered operation. The hub is either self-powered (draws less than 2 mA of upstream bus power) or bus-powered (limited to a 100 mA maximum of upstream power prior to being configured by the host controller). When configured as a bus-powered device, the SMSC hub consumes less than 100 mA of current prior to being configured. After configuration, the bus-powered SMSC hub (along with all associated hub circuitry, any embedded devices if part of a Compound Device, and 100 mA per externally available downstream port) must consume no more than 500 mA of upstream VBUS current. The current consumption is system dependent, and the OEM must ensure that the USB 2.0 Specification is not violated. When configured as a self-powered device, <1 mA of upstream VBUS current is consumed and all ports are available, with each port being capable of sourcing 500 mA of current. '0' = Bus-powered operation '1' = Self-powered operation
6	Reserved	Always reads '0'.
5	HS_DISABLE	Hi-Speed Disable: Disables the capability to attach as either a Hi-/Full-Speed device, and forces attachment as Full-Speed only (i.e. no Hi-Speed support). '0' = Hi-/Full-Speed '1' = Full-Speed-Only (Hi-Speed disabled!)
4	Reserved	Always reads '0'.
3	EOP_DISABLE	EOP Disable: Disables EOP generation of EOF1 when in Full-Speed mode. During FS operation only, this permits the hub to send EOP if no downstream traffic is detected at EOF1. See Section 11.3.1 of the USB 2.0 Specification for additional details. Note: generation of an EOP at the EOF1 point may prevent a Host Controller (operating in FS mode) from placing the USB bus in suspend. '0' = An EOP is generated at the EOF1 point if no traffic is detected. '1' = EOP generation at EOF1 is disabled (Note: This is normal USB operation). Note: This is a rarely used feature in the PC environment, existing drivers may not have been thoroughly debugged with this feature enabled. It is included because it is a permitted feature in Chapter 11 of the USB 2.0 Specification.
2:1	CURRENT_SNS	Over-Current Sense: Selects current sensing on a port-by-port basis, all ports ganged, or none (only for bus-powered hubs). The ability to support current sensing on a port or ganged basis is dependent upon the hardware implementation. '00' = Ganged sensing (all ports together) '01' = Individual port-by-port '1x' = Over-current sensing not supported (must only be used with bus-powered configurations!)
0	PORT_PWR	Port Power Switching: Enables power switching on all ports simultaneously (ganged), or port power is individually switched on and off on a port-by-port basis (individual). The ability to support power enabling on a port or ganged basis is dependent upon the hardware implementation. '0' = Ganged switching (all ports together) '1' = Individual port-by-port switching

7.3.5.8 E5h: Configuration Data Byte 2 (CFG_DAT_BYT2)

BIT	NAME	DESCRIPTION
7:6	Reserved	Always reads '0'.
5:4	OC_TIMER	OverCurrent Timer: Over-current Timer delay. 00 = 50 ns 01 = 100 ns 10 = 200 ns 11 = 400 ns
3	COMPOUND	Compound Device: Allows OEM to indicate that the hub is part of a compound (see the USB 2.0 Specification for definition) device. The applicable port(s) must also be defined as having a "non-removable device". When configured via strapping options, declaring a port as non-removable automatically causes the hub controller to report that it is part of a Compound Device. '0' = No '1' = Yes, the hub is part of a Compound Device
2:0	Always reads '0'.	Always reads '0'.

7.3.5.9 E6h: Configuration Data Byte 3 (CFG_DAT_BYT3)

BIT	NAME	DESCRIPTION
7:4	Reserved	Always reads '0'.
3	PRTMAP_EN	Port mapping enable: Selects the method used by the hub to assign port numbers and disable ports. '0' = Standard Mode. Strap options or the following registers are used to define which ports are enabled, and the ports are mapped as Port 'n' on the hub is reported as Port 'n' to the host, unless one of the ports is disabled, then the higher numbered ports are remapped in order to report contiguous port numbers to the host. Register 300Ah: Port Disable For Self-Powered Operation (Reset = 0x00). Register 300Bh: Port Disable For Bus-Powered Operation (Reset = 0x00). '1' = Port map mode. The mode enables remapping via the registers defined below. Register 30FBh: Port Map 12 (Reset = 0x00) Register 30FCh: Port Map 3 (Reset = 0x00)
2:0	Reserved	Always reads '0'.

7.3.5.10 E7h: Non-Removable Device

BIT	BYTE NAME	DESCRIPTION
7:0	NR_DEVICE	Indicates which port(s) include non-removable devices. '0' = Port is removable '1' = Port is non-removable Informs the host if one of the active ports has a permanent device that is undetachable from the hub. (Note: The device must provide its own descriptor data.) When using the internal default option, the NON_REM[1:0] pins will designate the appropriate ports as being non-removable. Bit 7= Reserved Bit 6= Reserved Bit 5= Reserved Bit 4= Reserved Bit 3= Controls physical port 3 Bit 2= Controls physical port 2 Bit 1= Controls physical port 1 Bit 0= Reserved, always = '0' Note: Bit 1 must be set to a '1' by the firmware for proper identification of the card reader as a non-removable device.

7.3.5.11 E8h: Port Disable For Self-Powered Operation

BIT	BYTE NAME	DESCRIPTION
7:0	PORT_DIS_SP	Disables 1 or more ports. '0' = Port is available '1' = Port is disabled During self-powered operation this register selects the ports which will be permanently disabled. The ports are unavailable to be enabled or enumerated by a Host Controller. The ports can be disabled in any order since the internal logic will automatically report the correct number of enabled ports to the USB host and will reorder the active ports in order to ensure proper function. Bit 7= Reserved Bit 6= Reserved Bit 5= Reserved Bit 4= Reserved Bit 3= Controls physical port 3 Bit 2= Controls physical port 2 Bit 1= Controls physical port 1 Bit 0= Reserved, always = '0'

7.3.5.12 E9h: Port Disable For Bus-Powered Operation

BIT	BYTE NAME	DESCRIPTION
7:0	PORT_DIS_BP	Disables 1 or more ports. '0' = Port is available '1' = Port is disabled During self-powered operation, this register selects the ports which will be permanently disabled. The ports are unavailable to be enabled or enumerated by a Host Controller. The ports can be disabled in any order, the internal logic will automatically report the correct number of enabled ports to the USB host and will reorder the active ports in order to ensure proper function. When using the internal default option, the PRT_DIS[1:0] pins will disable the appropriate ports. Bit 7= Reserved Bit 6= Reserved Bit 5= Reserved Bit 4= Reserved Bit 3= Controls physical port 3 Bit 2= Controls physical port 2 Bit 1= Controls physical port 1 Bit 0 is Reserved, always = '0'

7.3.5.13 EAh: Max Power For Self-Powered Operation

BIT	BYTE NAME	DESCRIPTION
7:0	MAX_PWR_SP	Max Power Self_Powered: Value in 2 mA increments that the hub consumes from an upstream port (VBUS) when operating as a self-powered hub. This value includes the hub silicon along with the combined power consumption (from VBUS) of all associated circuitry on the board. This value also includes the power consumption of a permanently attached peripheral if the hub is configured as a Compound Device, and the embedded peripheral reports 0 mA in its descriptors. Note: The USB 2.0 Specification does not permit this value to exceed 100 mA.

7.3.5.14 EBh: Max Power For Bus-Powered Operation

BIT	BYTE NAME	DESCRIPTION
7:0	MAX_PWR_BP	Max Power Bus_Powered: Value in 2 mA increments that the hub consumes from an upstream port (VBUS) when operating as a bus-powered hub. This value includes the hub silicon along with the combined power consumption (from VBUS) of all associated circuitry on the board. This value also includes the power consumption of a permanently attached peripheral if the hub is configured as a Compound Device, and the embedded peripheral reports 0 mA in its descriptors.

7.3.5.15 ECh: Hub Controller Max Current For Self-Powered Operation

BIT	BYTE NAME	DESCRIPTION
7:0	HC_MAX_C_SP	Hub Controller Max Current Self-Powered: Value in 2 mA increments that the hub consumes from an upstream port (VBUS) when operating as a self-powered hub. This value includes the hub silicon along with the combined power consumption (from VBUS) of all associated circuitry on the board. This value does NOT include the power consumption of a permanently attached peripheral if the hub is configured as a Compound Device. Note: The USB 2.0 Specification does not permit this value to exceed 100 mA. A value of 50 (decimal) indicates 100 mA, which is the default value.

7.3.5.16 EDh: Hub Controller Max Current For Bus-Powered Operation

BIT	BYTE NAME	DESCRIPTION
7:0	HC_MAX_C_BP	Hub Controller Max Current Bus-Powered: Value in 2 mA increments that the hub consumes from an upstream port (VBUS) when operating as a bus-powered hub. This value will include the hub silicon along with the combined power consumption (from VBUS) of all associated circuitry on the board. This value will NOT include the power consumption of a permanently attached peripheral if the hub is configured as a Compound Device. A value of 50 (decimal) would indicate 100 mA, which is the default value.

7.3.5.17 EEh: Power-On Time

BIT	BYTE NAME	DESCRIPTION
7:0	PWR_ON_TIME	Power-On Time: The length of time that it takes (in 2 ms intervals) from the time the host initiated power-on sequence begins on a port until power is adequate on that port. System software uses this value to determine how long to wait before accessing a powered-on port.

7.3.5.18 EFh: Boost_Up

BIT	NAME	DESCRIPTION
7:2	Reserved	Reserved
1:0	BOOST_IOUT	USB electrical signaling drive strength Boost Bit for the Upstream Port 'A'. '00' = Normal electrical drive strength = No boost '01' = Elevated electrical drive strength = Low (approximately 4% boost) '10' = Elevated electrical drive strength = Medium (approximately 8% boost) '11' = Elevated electrical drive strength = High (approximately 12% boost) Note: "Boost" could result in non-USB Compliant parameters. OEM should use a '00' value unless specific implementation issues require additional signal boosting to correct for degraded USB signalling levels.

7.3.5.19 F0h: Boost_3:0

BIT	NAME	DESCRIPTION
7:6	Reserved	Always reads '0'.
5:4	BOOST_IOUT_3	Upstream USB electrical signaling drive strength Boost Bit for Downstream Port '3'. '00' = Normal electrical drive strength = No boost '01' = Elevated electrical drive strength = Low (approximately 4% boost) '10' = Elevated electrical drive strength = Medium (approximately 8% boost) '11' = Elevated electrical drive strength = High (approximately 12% boost)
3:2	BOOST_IOUT_2	Upstream USB electrical signaling drive strength Boost Bit for Downstream Port '2'. '00' = Normal electrical drive strength = No boost '01' = Elevated electrical drive strength = Low (approximately 4% boost) '10' = Elevated electrical drive strength = Medium (approximately 8% boost) '11' = Elevated electrical drive strength = High (approximately 12% boost) Note: "Boost" could result in non-USB Compliant parameters. OEM should use a '00' value unless specific implementation issues require additional signal boosting to correct for degraded USB signalling levels.
1:0	Reserved	Always reads '0'.

7.3.5.20 F1h: Port Swap

BIT	BYTE NAME	DESCRIPTION
7:0	PRT_SWP	Port Swap: Swaps the Upstream and Downstream USB DP and DM Pins for ease of board routing to devices and connectors. '0' = USB D+ functionality is associated with the DP pin and D- functionality is associated with the DM pin. '1' = USB D+ functionality is associated with the DM pin and D- functionality is associated with the DP pin. Bit 7= Reserved Bit 6= Reserved Bit 5= Reserved Bit 4= Reserved Bit 3= Controls physical port 3 Bit 2= Controls physical port 2 Bit 1= Reserved Bit 0= Controls physical port 0

7.3.5.21 F2h: Port Map 12

BIT	BYTE NAME	DESCRIPTION																												
7:0	PRTM12	Port map register for ports 1 & 2. When a hub is enumerated by a USB Host Controller, the hub is only permitted to report how many ports it has; the hub is not permitted to select a numerical range or assignment. The Host Controller will number the downstream ports of the hub starting with the number '1', up to the number of ports that the hub reported having. The host's port number is referred to as "logical port number" and the physical port on the hub is the "physical port number". When remapping mode is enabled (see PRTMAP_EN in Register 08h: Configuration Data Byte 3) the hub's downstream port numbers can be remapped to different logical port numbers (assigned by the host). Note: OEM must ensure that contiguous logical port numbers are used, starting from number '1' up to the maximum number of enabled ports; this ensures that the hub's ports are numbered in accordance with the way a host will communicate with the ports.																												
		Table 7.4 Port Map Register for Ports 1 & 2 <table border="1"> <tr> <td>Bit [7:4]</td><td>'0000'</td><td>Physical Port 2 is Disabled</td></tr> <tr> <td></td><td>'0001'</td><td>Physical Port 2 is mapped to Logical Port 1</td></tr> <tr> <td></td><td>'0010'</td><td>Physical Port 2 is mapped to Logical Port 2</td></tr> <tr> <td></td><td>'0011'</td><td>Physical Port 2 is mapped to Logical Port 3</td></tr> <tr> <td></td><td>'0100' to '1111'</td><td>Illegal; Do Not Use</td></tr> <tr> <td>Bit [3:0]</td><td>'0000'</td><td>Physical Port 1 is Disabled</td></tr> <tr> <td></td><td>'0001'</td><td>Physical Port 1 is mapped to Logical Port 1</td></tr> <tr> <td></td><td>'0010'</td><td>Physical Port 1 is mapped to Logical Port 2</td></tr> <tr> <td></td><td>'0011'</td><td>Physical Port 1 is mapped to Logical Port 3</td></tr> <tr> <td></td><td>'0100' to '1111'</td><td>Illegal; Do Not Use</td></tr> </table>	Bit [7:4]	'0000'	Physical Port 2 is Disabled		'0001'	Physical Port 2 is mapped to Logical Port 1		'0010'	Physical Port 2 is mapped to Logical Port 2		'0011'	Physical Port 2 is mapped to Logical Port 3		'0100' to '1111'	Illegal; Do Not Use	Bit [3:0]	'0000'	Physical Port 1 is Disabled		'0001'	Physical Port 1 is mapped to Logical Port 1		'0010'	Physical Port 1 is mapped to Logical Port 2		'0011'	Physical Port 1 is mapped to Logical Port 3	
Bit [7:4]	'0000'	Physical Port 2 is Disabled																												
	'0001'	Physical Port 2 is mapped to Logical Port 1																												
	'0010'	Physical Port 2 is mapped to Logical Port 2																												
	'0011'	Physical Port 2 is mapped to Logical Port 3																												
	'0100' to '1111'	Illegal; Do Not Use																												
Bit [3:0]	'0000'	Physical Port 1 is Disabled																												
	'0001'	Physical Port 1 is mapped to Logical Port 1																												
	'0010'	Physical Port 1 is mapped to Logical Port 2																												
	'0011'	Physical Port 1 is mapped to Logical Port 3																												
	'0100' to '1111'	Illegal; Do Not Use																												

7.3.5.22 F3h: Port Map 3

BIT	BYTE NAME	DESCRIPTION																														
7:0	PRTM3	Port map register for port 3. When a hub is enumerated by a USB Host Controller, the hub is only permitted to report how many ports it has; the hub is not permitted to select a numerical range or assignment. The Host Controller will number the downstream ports of the hub starting with the number '1', up to the number of ports that the hub reported having. The host's port number is referred to as "logical port number" and the physical port on the hub is the "physical port number". When remapping mode is enabled (see PRTMAP_EN in Register 08h: Configuration Data Byte 3) the hub's downstream port numbers can be remapped to different logical port numbers (assigned by the host). Note: OEM must ensure that contiguous logical port numbers are used, starting from number '1' up to the maximum number of enabled ports; this ensures that the hub's ports are numbered in accordance with the way a host will communicate with the ports.																														
Table 7.5 Port Map Register for Port 3 <table border="1"> <tr> <td>Bit [7:4]</td><td>'0000'</td><td>Reserved</td></tr> <tr> <td></td><td>'0001'</td><td>Reserved</td></tr> <tr> <td></td><td>'0010'</td><td>Reserved</td></tr> <tr> <td></td><td>'0011'</td><td>Reserved</td></tr> <tr> <td></td><td>'0100' to '1111'</td><td>Illegal; Do Not Use</td></tr> <tr> <td>Bit [3:0]</td><td>'0000'</td><td>Physical Port 3 is Disabled</td></tr> <tr> <td></td><td>'0001'</td><td>Physical Port 3 is mapped to Logical Port 1</td></tr> <tr> <td></td><td>'0010'</td><td>Physical Port 3 is mapped to Logical Port 2</td></tr> <tr> <td></td><td>'0011'</td><td>Physical Port 3 is mapped to Logical Port 3</td></tr> <tr> <td></td><td>'0100' to '1111'</td><td>Illegal; Do Not Use</td></tr> </table>			Bit [7:4]	'0000'	Reserved		'0001'	Reserved		'0010'	Reserved		'0011'	Reserved		'0100' to '1111'	Illegal; Do Not Use	Bit [3:0]	'0000'	Physical Port 3 is Disabled		'0001'	Physical Port 3 is mapped to Logical Port 1		'0010'	Physical Port 3 is mapped to Logical Port 2		'0011'	Physical Port 3 is mapped to Logical Port 3		'0100' to '1111'	Illegal; Do Not Use
Bit [7:4]	'0000'	Reserved																														
	'0001'	Reserved																														
	'0010'	Reserved																														
	'0011'	Reserved																														
	'0100' to '1111'	Illegal; Do Not Use																														
Bit [3:0]	'0000'	Physical Port 3 is Disabled																														
	'0001'	Physical Port 3 is mapped to Logical Port 1																														
	'0010'	Physical Port 3 is mapped to Logical Port 2																														
	'0011'	Physical Port 3 is mapped to Logical Port 3																														
	'0100' to '1111'	Illegal; Do Not Use																														

7.3.5.23 F4h-FBh: Reserved

BYTE	BYTE NAME	DESCRIPTION
7:0	Reserved	Reserved.

7.3.5.24 FCh-FFh: Non-volatile Storage Signature

BYTE	BYTE NAME	STRING	DESCRIPTION
3:0	NVSTORE_SIG	"ATA2"	This signature is used to verify the validity of the data in the configuration area. The signature must be set to 'ATA2' for USB2640i/USB2641i.

7.3.6 I²C EEPROM

The I²C EEPROM interface implements a subset of the I²C Master Specification (Please refer to the Philips Semiconductor Standard I²C-Bus Specification for details on I²C bus protocols). The device's I²C EEPROM interface is designed to attach to a single "dedicated" I²C EEPROM, and it conforms to the Standard-mode I²C Specification (100 kbps transfer rate and 7-bit addressing) for protocol and electrical compatibility.

Note: Extensions to the I²C Specification are not supported.

The device acts as the master and generates the serial clock SCL, controls the bus access (determines which device acts as the transmitter and which device acts as the receiver), and generates the START and STOP conditions.

7.3.6.1 Implementation Characteristics

The device will only access an EEPROM using the sequential read protocol.

7.3.6.2 Pull-Up Resistor

The circuit board designer is required to place external pull-up resistors (10 kΩ recommended) on the SDA/SMBDATA & SCL/SMBCLK/CFG_SEL0 lines (per SMBus 1.0 Specification, and EEPROM manufacturer guidelines) to VDD33 in order to assure proper operation.

7.3.7 In-Circuit EEPROM Programming

The EEPROM can be programmed via automatic testing test equipment (ATE) by pulling nRESET low which tri-states the device's EEPROM interface and allows an external source to program the EEPROM.

7.4 Default Configuration Option:

The SMSC device can be configured via its internal default configuration. Please see [Section 7.3.2, "EEPROM Data Descriptor"](#) for specific details on how to enable default configuration. Please refer to [Table 7.1](#) for the internal default values that are loaded when this option is selected.

7.5 Reset

There are two different resets that the device experiences. One is a hardware reset (either from the internal POR reset circuit or via the nRESET pin) and the second is a USB Bus Reset.

7.5.1 Internal POR Hardware Reset

All reset timing parameters are guaranteed by design.

7.5.2 External Hardware nRESET

A valid hardware reset is defined as assertion of nRESET for a minimum of 1 μ s after all power supplies are within operating range. While reset is asserted, the device (and its associated external circuitry) consumes less than 500 μ A of current from the upstream USB power source.

Assertion of nRESET (external pin) causes the following:

1. All downstream ports are disabled, and PRTCTL power to downstream devices is removed.
2. The PHYs are disabled, and the differential pairs will be in a high-impedance state.
3. All transactions immediately terminate; no states are saved.
4. All internal registers return to the default state (in most cases, 00h).
5. The external crystal oscillator is halted.
6. The PLL is halted.

7.5.2.1 nRESET for EEPROM Configuration

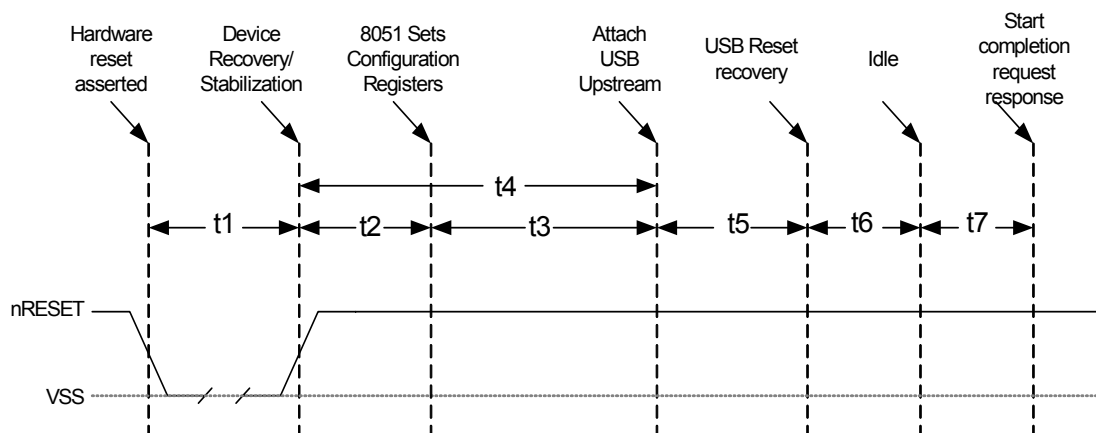


Figure 7.1 nRESET Timing for EEPROM Mode

Table 7.6 nRESET Timing for EEPROM Mode

NAME	DESCRIPTION	MIN	TYP	MAX	UNITS
t1	nRESET asserted.	1			μ sec
t2	Device recovery/stabilization.			500	μ sec
t3	8051 programs device configuration		20	50	msec
t4	USB attach (See Note).			100	msec
t5	Host acknowledges attach and signals USB reset.	100			msec
t6	USB idle.		Undefined		msec
t7	Completion time for requests (with or without data stage).			5	msec

Note: All power supplies must have reached the operating levels mandated in [Chapter 10, DC Parameters](#), prior to (or coincident with) the assertion of nRESET.

7.5.3 USB Bus Reset

In response to the upstream port signaling a reset to the device, the device does the following:

Note: The device does not propagate the upstream USB reset to downstream devices.

1. Sets default address to '0'.
2. Sets configuration to: Unconfigured.
3. Negates PRTCTL[3:2] to all downstream ports.
4. Clears all TT buffers.
5. Moves device from suspended to active (if suspended).
6. Complies with Section 11.10 of the USB 2.0 Specification for behavior after completion of the reset sequence.

The host then configures the device and the device's downstream port devices in accordance with the USB 2.0 Specification.

Chapter 8 Pin Reset States

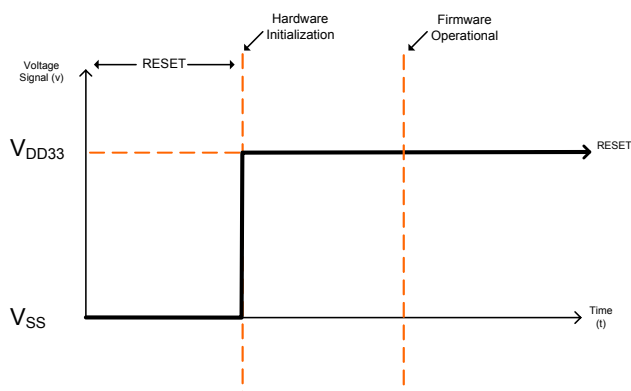


Figure 8.1 Pin Reset States

Table 8.1 Legend for Pin Reset States Table

SYMBOL	DESCRIPTION
Y	Hardware enables function
0	Output low
1	Output high
--	Hardware disables function
Z	Hardware disables output driver (high impedance)
PU	Hardware enables pull-up
PD	Hardware enables pull-down
HW	Hardware controls function, but state is protocol dependent
(FW)	Firmware controls function through registers
VDD	Hardware supplies power through pin, applicable only to CARD_PWR pin
none	Hardware disables pad

8.1 Pin Reset States

Table 8.2 USB2640i Pin Reset States

PIN	PIN NAME	RESET STATE			
		FUNCTION	OUTPUT	PU/ PD	INPUT
1	USBDN_DM2	USBDN_DM2	0	PD	--
2	USBDN_DP2	USBDN_DP2	0	PD	--

Table 8.2 USB2640i Pin Reset States (continued)

PIN	PIN NAME	RESET STATE			
		FUNCTION	OUTPUT	PU/ PD	INPUT
3	USBDN_DM3	USBDN_DM3	0	PD	--
4	USBDN_DP3	USBDN_DP3	0	PD	--
6	PRTCTL2	PRTCTL	0	--	--
7	PRTCTL3	PRTCTL	0	--	--
8	SPI_CE_n	SPI_CE_n	1	--	--
9	SPI_CLK / GPIO4 / SCL	GPIO	0	--	--
10	SPI_DO / GPIO5 / SDA / SPI_SPD_SEL	GPIO	Z	PD	Y
11	SPI_DI	SPI_DI	Z	PD	Y
13	xD_D4 / GPIO6 / SD_WP / MS_SCLK	GPIO	0	--	--
14	GPIO15 / SD_nCD	GPIO	Z	PU	Y
17	xD_D3 / SD_D1 / MS_D5	none	Z	--	--
18	xD_D2 / SD_D0 / MS_D4	none	Z	--	--
19	xD_D1 / SD_D7 / MS_D6	none	Z	--	--
20	xD_D0 / SD_D6 / MS_D7	none	Z	--	--
21	xD_nWP / SD_CLK / MS_BS	none	Z	--	--
22	xD_nWE	none	Z	--	--
23	xD_ALE / SD_D5 / MS_D1	none	Z	--	--
24	xD_CLE / SD_CMD / MS_D0	none	Z	--	--
26	xD_nCE	none	Z	--	--
27	xD_nRE	none	Z	--	--
28	xD_nB/R	none	Z	--	--
29	GPIO14 / xD_nCD	GPIO	Z	PU	Y
30	xD_D7 / SD_D4 / MS_D2	none	Z	--	--
31	GPIO12 / MS_INS	GPIO	Z	PU	Y
32	xD_D6 / SD_D3 / MS_D3	none	Z	--	--
33	xD_D5 / SD_D2	none	Z	--	--
35	GPIO10(CARD_PWR)	GPIO	Z	--	--

Table 8.2 USB2640i Pin Reset States (continued)

		RESET STATE			
PIN	PIN NAME	FUNCTION	OUTPUT	PU/ PD	INPUT
36	GPIO2 / RXD	GPIO	0	--	--
37	GPIO1 / LED / TXD	GPIO1	0	--	--
38	nRESET	nRESET	Z	--	Y
39	VBUS_DET	VBUS_DET	Z	--	Y
40	TEST	TEST	Z	--	Y
42	USB+	USB+	Z	--	--
43	USB-	USB-	Z	--	--
44	XTAL2				
45	XTAL1 (CLKIN)				
47	RBIAS				

Table 8.3 USB2641i Pin Reset States

		RESET STATE			
PIN	PIN NAME	FUNCTION	OUTPUT	PU/ PD	INPUT
1	USBDN_DM2	USBDN_DM2	0	PD	--
2	USBDN_DP2	USBDN_DP2	0	PD	--
3	USBDN_DM3	USBDN_DM3	0	PD	--
4	USBDN_DP3	USBDN_DP3	0	PD	--
6	PRTCTL2	PRTCTL	0	--	--
7	PRTCTL3	PRTCTL	0	--	--
8	SPI_CE_n	SPI_CE_n	1	--	--
9	SPI_CLK / GPIO4 / SCL	GPIO	0	--	--
10	SPI_DO / GPIO5 / SDA / SPI_SPD_SEL	GPIO	Z	PD	Y
11	SPI_DI	SPI_DI	Z	PD	Y
13	GPIO6 / SD_WP / MS_SCLK	GPIO	0	--	--
14	GPIO15 / SD_nCD	GPIO	Z	PU	Y
17	SD_D1 / MS_D5	none	Z	--	--

Table 8.3 USB2641i Pin Reset States (continued)

PIN	PIN NAME	RESET STATE			
		FUNCTION	OUTPUT	PU/ PD	INPUT
18	SD_D0 / MS_D4	none	Z	--	--
19	SD_D7 / MS_D6	none	Z	--	--
20	SD_D6 / MS_D7	none	Z	--	--
21	SD_CLK / MS_BS	none	Z	--	--
23	SD_D5 / MS_D1	none	Z	--	--
24	SD_CMD / MS_D0	none	Z	--	--
29	GPIO14	GPIO	Z	PU	Y
30	SD_D4 / MS_D2	none	Z	--	--
31	GPIO12 / MS_INS	GPIO	Z	PU	Y
32	SD_D3 / MS_D3	none	Z	--	--
33	SD_D2	none	Z	--	--
35	GPIO10(CARD_PWR)	GPIO	Z	--	--
36	GPIO2 / RXD	GPIO	0	--	--
37	GPIO1 / LED / TXD	GPIO1	0	--	--
38	nRESET	nRESET	Z	--	Y
39	VBUS_DET	VBUS_DET	Z	--	Y
40	TEST	TEST	Z	--	Y
42	USB+	USB+	Z	--	--
43	USB-	USB-	Z	--	--
44	XTAL2				
45	XTAL1 (CLKIN)				
47	RBIAS				

Chapter 9 AC Specifications

9.1 Oscillator/Crystal

Parallel Resonant, Fundamental Mode, 24 MHz ± 350 ppm.

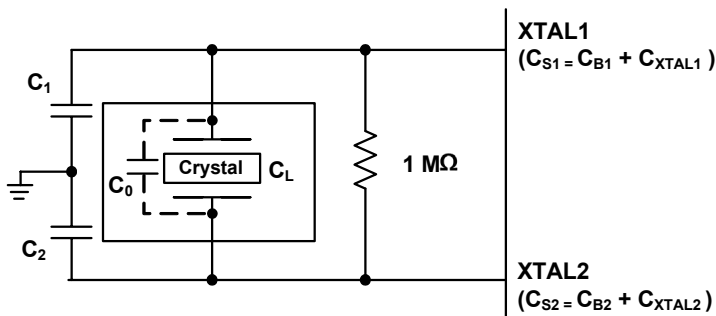


Figure 9.1 Typical Crystal Circuit

Table 9.1 Crystal Circuit Legend

SYMBOL	DESCRIPTION	IN ACCORDANCE WITH
C_0	Crystal shunt capacitance	Crystal manufacturer's specification (See Note 9.1)
C_L	Crystal load capacitance	
C_B	Total board or trace capacitance	OEM board design
C_S	Stray capacitance	SMSC IC and OEM board design
C_{XTAL}	XTAL pin input capacitance	SMSC IC
C_1 C_2	Load capacitors installed on OEM board	Calculated values based on Figure 9.2, "Capacitance Formulas" (See Note 9.2)

$$C_1 = 2 \times (C_L - C_0) - C_{S1}$$

$$C_2 = 2 \times (C_L - C_0) - C_{S2}$$

Figure 9.2 Capacitance Formulas

Note 9.1 C_0 is usually included (subtracted by the crystal manufacturer) in the specification for C_L and should be set to '0' for use in the calculation of the capacitance formulas in Figure 9.2, "Capacitance Formulas". However, the OEM PCB itself may present a parasitic capacitance between XTAL1 and XTAL2. For an accurate calculation of C_1 and C_2 , take the parasitic capacitance between traces XTAL1 and XTAL2 into account.

Note 9.2 Each of these capacitance values is typically approximately 18 pF.

9.2 Ceramic Resonator

24 MHz $\pm$ 350 ppm

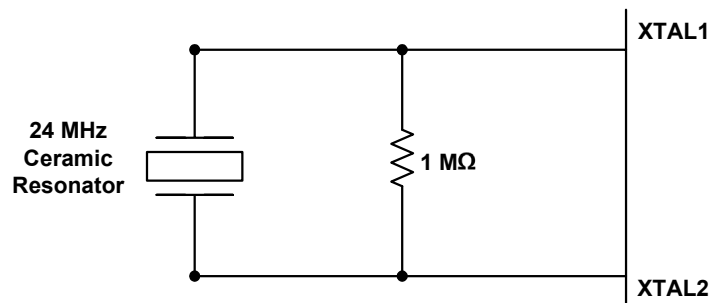


Figure 9.3 Ceramic Resonator Usage with SMSC IC

9.3 External Clock

50% Duty cycle $\pm$ 10%, 24 MHz $\pm$ 350 ppm, Jitter < 100 ps rms.

The external clock is recommended to conform to the signaling level designated in the JESD76-2 specification on 1.8 V CMOS Logic. XTAL2 should be treated as a no connect.

9.3.1 I²C EEPROM

Frequency is fixed at 58.6 kHz $\pm$ 20%

9.3.2 USB 2.0

The SMSC device conforms to all voltage, power, and timing characteristics and specifications as set forth in the USB 2.0 Specification. Please refer to the USB 2.0 Specification for more information.

Chapter 10 DC Parameters

10.1 Maximum Guaranteed Ratings

PARAMETER	SYMBOL	MIN	MAX	UNITS	COMMENTS
Storage Temperature	T_{STOR}	-55	150	°C	
Lead Temperature				°C	Please refer to JEDEC specification J-STD-020D.
3.3 V supply voltage	V_{DD33}	-0.5	4.0	V	
Voltage on USB+ and USB- pins		-0.5	$(3.3 \text{ V supply voltage} + 2) \leq 6$	V	
Voltage on GPIO10		-0.5	$V_{\text{DD33}} + 0.3$	V	When internal power FET operation of these pins are enabled, these pins may be simultaneously shorted to ground or any voltage up to 3.63 V indefinitely, without damage to the device as long as V_{DD33} is less than 3.63 V and T_A is less than 70°C.
Voltage on any signal pin		-0.5	$V_{\text{DD33}} + 0.3$	V	
Voltage on XTAL1		-0.5	3.6	V	
Voltage on XTAL2		-0.5	2.0	V	

Note 10.1 Stresses above the specified parameters may cause permanent damage to the device. This is a stress rating only. Functional operation of the device at any condition above those indicated in the operation sections of this specification is not implied.

Note 10.2 When powering this device from laboratory or system power supplies the Absolute Maximum Ratings must not be exceeded or device failure can result. Some power supplies exhibit voltage spikes on their outputs when the AC power is switched on or off. In addition, voltage transients on the AC power line may appear on the DC output. When this possibility exists, a clamp circuit should be used.

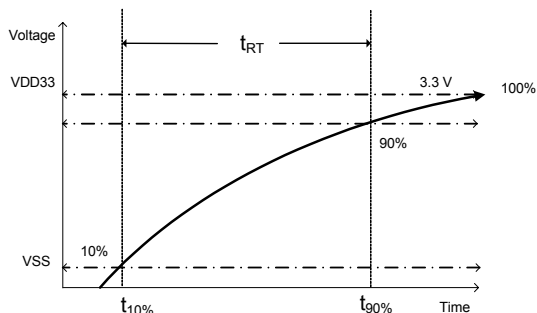


Figure 10.1 Supply Rise Time Models

10.2 Operating Conditions

PARAMETER	SYMBOL	MIN	MAX	UNITS	COMMENTS
Operating Temperature	T_A	-40	85	°C	Ambient temperature in still air.
3.3 V supply voltage	V_{DD33}	3.0	3.6	V	A 3.3 V regulator with an output tolerance of 1% must be used if the output of the internal power FETs must support a 5% tolerance.
3.3 V supply rise time	t_{RT}	0	400	μ s	(Figure 10.1)
Voltage on USB+ and USB- pins		-0.3	5.5	V	If any 3.3 V supply voltage drops below 3.0 V, then the MAX becomes: $(3.3 \text{ V supply voltage}) + 0.5 \leq 5.5$
Voltage on any signal pin		-0.3	V_{DD33}	V	
Voltage on XTAL1		-0.3	2.0	V	
Voltage on XTAL2		-0.3	2.0	V	

10.3 DC Electrical Characteristics

PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS	COMMENTS
I, IPU, IPD Type Input Buffer						
Low Input Level	V _{ILI}	2.0	72	0.8	V	TTL Levels
High Input Level	V _{IHI}			V		
Pull Down	PD			μA		
Pull Up	PU			μA		
IS Type Input Buffer						
Low Input Level	V _{ILI}	2.0	420	0.8	V	TTL Levels
High Input Level	V _{IHI}			V		
Hysteresis	V _{HYSI}			mV		
ICLK Input Buffer						
Low Input Level	V _{ILCK}	1.4		0.5	V	V _{IN} = 0 to V _{DD33}
High Input Level	V _{IHCK}			V		
Input Leakage	I _{IL}			+10	μA	

PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS	COMMENTS
Input Leakage (All I and IS buffers)						
Low Input Leakage	I_{IL}	-10		+10	μA	$V_{IN} = 0$
High Input Leakage	I_{IH}	-10		+10	μA	$V_{IN} = V_{DD33}$
O12 Type Buffer						
Low Output Level	V_{OL}			0.4	V	$I_{OL} = 12 \text{ mA @ } V_{DD33} = 3.3 \text{ V}$
High Output Level	V_{OH}	$V_{DD33} - 0.4$			V	$I_{OH} = -12 \text{ mA @ } V_{DD33} = 3.3 \text{ V}$
Output Leakage	I_{OL}	-10		+10	μA	$V_{IN} = 0 \text{ to } V_{DD33}$ (Note 10.3)
I/O12, I/O12PU & I/O12PD Type Buffer						
Low Output Level	V_{OL}			0.4	V	$I_{OL} = 12 \text{ mA @ } V_{DD33} = 3.3 \text{ V}$
High Output Level	V_{OH}	$V_{DD33} - 0.4$			V	$I_{OH} = -12 \text{ mA @ } V_{DD33} = 3.3 \text{ V}$
Output Leakage	I_{OL}	-10		+10	μA	$V_{IN} = 0 \text{ to } V_{DD33}$ (Note 10.3)
Pull Down	PD		72		μA	
Pull Up	PU		58		μA	
IO-U						(Note 10.4)
I-R						(Note 10.5)
Integrated Power FET Set to 100 mA						
Output Current (Note 10.6)	I_{OUT}	100			mA	$V_{dropFET} = 0.22 \text{ V}$
Short Circuit Current Limit	I_{SC}			140	mA	$V_{outFET} = 0 \text{ V}$
On Resistance (Note 10.6)	$R_{DS(on)}$			2.1	Ω	$I_{FET} = 70 \text{ mA}$
Output Voltage Rise Time	$t_{DS(on)}$			800	μs	$C_{LOAD} = 10 \mu F$

PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS	COMMENTS
Integrated Power FET Set to 200 mA						
Output Current (Note 10.6)	I_{OUT}	200			mA	$V_{drop_{FET}} = 0.46\text{ V}$
Short Circuit Current Limit	I_{SC}			181	mA	$V_{out_{FET}} = 0\text{ V}$
On Resistance (Note 10.6)	$R_{DS(on)}$			2.1	Ω	$I_{FET} = 70\text{ mA}$
Output Voltage Rise Time	t_{DSON}			800	μs	$C_{LOAD} = 10\text{ }\mu\text{F}$
Supply Current Unconfigured						
Hi-Speed Host	$I_{CCINTHS}$		65	80	mA	
Full Speed Host	$I_{CCINITFS}$		60	75	mA	
Supply Current Active	I_{CC}		280	315	mA	
Supply Current Suspend	I_{CSBYI}		420	650	μA	
Supply Current Reset	I_{RST}		205	425	μA	

Note 10.3 Output leakage is measured with the current pins in high impedance.

Note 10.4 See the USB 2.0 Specification, Chapter 7, for USB DC electrical characteristics

Note 10.5 RBIAS is a 3.3 V tolerant analog pin.

Note 10.6 Output current range is controlled by program software. The software disables the FET during short circuit condition.

10.4 Capacitance $T_A = 25^\circ\text{C}$; $f_c = 1\text{ MHz}$; $V_{DD33} = 3.3\text{ V}$

Table 10.1 Pin Capacitance

PARAMETER	SYMBOL	LIMITS			UNIT	TEST CONDITION
		MIN	TYP	MAX		
Clock Input Capacitance	C_{XTAL}			2	pF	All pins (except USB pins and pins under test) are tied to AC ground.
Input Capacitance	C_{IN}			10	pF	
Output Capacitance	C_{OUT}			20	pF	

Chapter 11 GPIO Usage

Table 11.1 USB2640i/USB2641i GPIO Usage

NAME	ACTIVE LEVEL	SYMBOL	DESCRIPTION
GPIO1	H	TxD / LED	Serial port transmit line / LED indicator
GPIO2	H	RxD	Serial port receive line
GPIO4	H	SCK	Serial EEPROM clock
GPIO5	H	SDA	Serial EEPROM data
GPIO6	L	SD_WP	Secure Digital card write protect detect
GPIO10	L	CRD_PWR_CTRL	Card power control
GPIO12	L	MS_nCD	Memory Stick card detect
GPIO14	L	xD_nCD	xD-Picture card detect
GPIO15	L	SD_nCD	Secure Digital card detect

Chapter 12 Package Outline

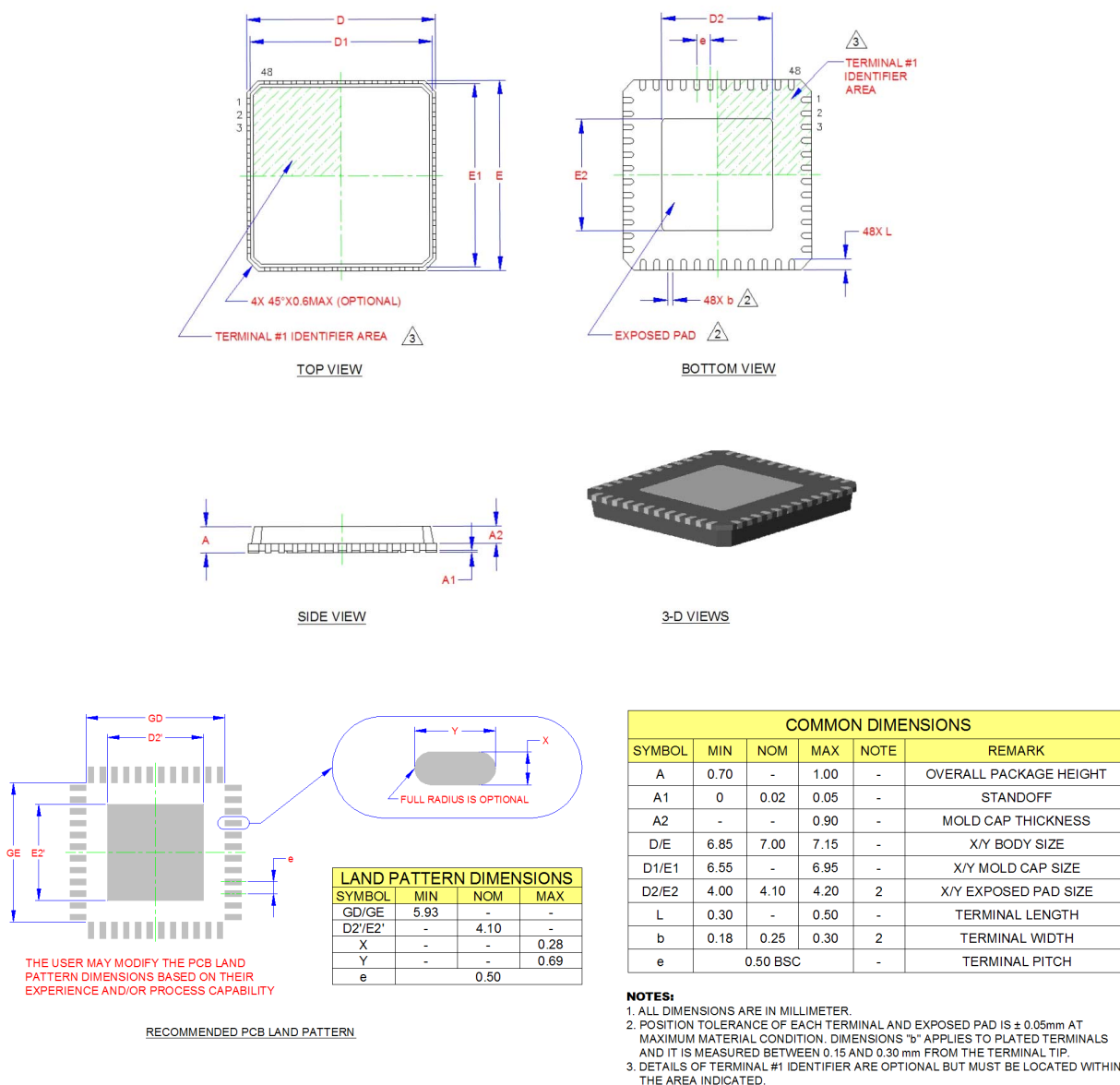


Figure 12.1 USB2640i/USB2641i 48-Pin QFN

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru

moschip.ru_4

moschip.ru_6

moschip.ru_9